DATA SHEET

旭曜科技 ORISE TECH



# SPLC783A

## 16COM/80SEG Controller/Driver

APR. 12, 2007

Version 1.7

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# 16COM / 80SEG CONTROLLER / DRIVER

## 1. GENERAL DESCRIPTION

The SPLC783A, a dot-matrix LCD controller and driver from ORISE, is a unique design for displaying alpha-numeric, Japanese-Kana characters and symbols. The SPLC783A provides two types of interfaces to MPU: 4-bit and 8-bit interfaces. The transferring speed of 8-bit is twice faster than 4-bit. A single SPLC783A is able to display up to two 16-character lines. By cascading with SPLC100 or SPLC063, the display capability can be extended. The CMOS technology ensures the power saves in the most efficient way and the performance keeps in the highest rank.

## 2. FEATURES

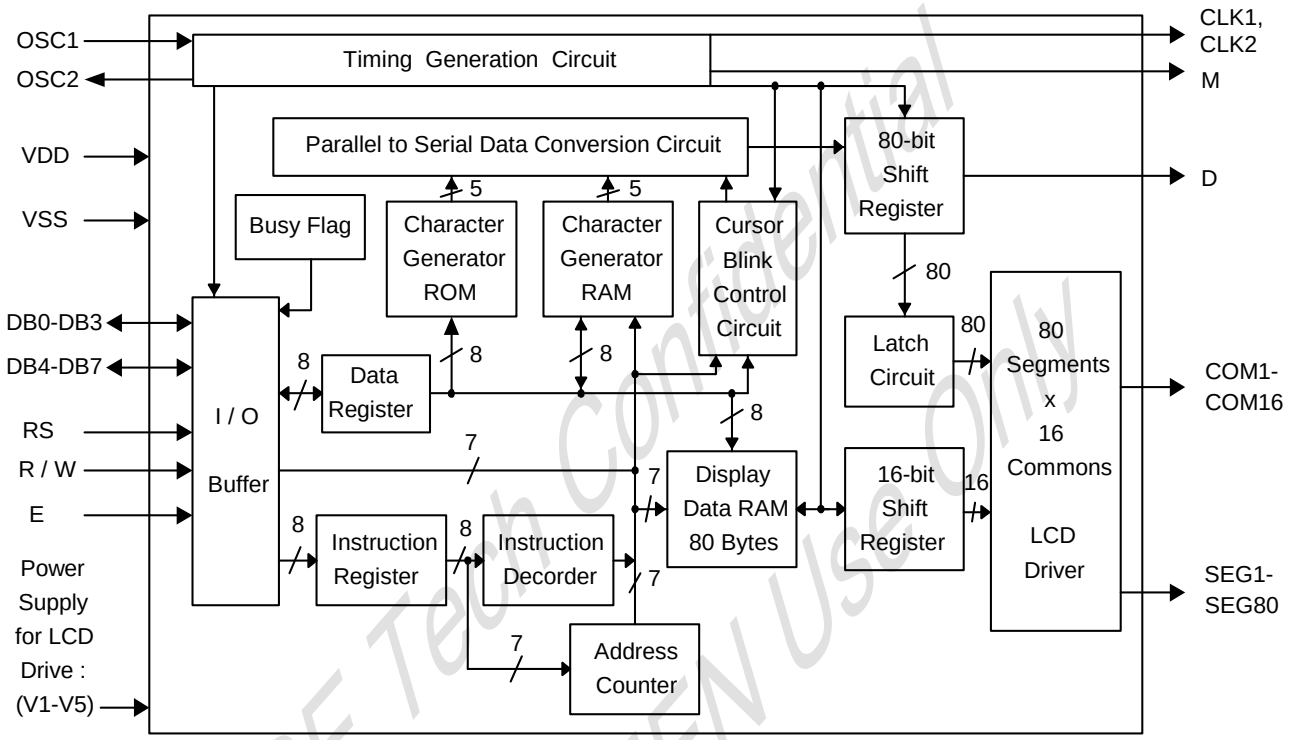
- Character generator ROM: 10880 bits
  - Character font 5 x 8 dots: 192 characters
  - Character font 5 x 10 dots: 64 characters
- Character generator RAM: 512 bits
  - Character font 5 x 8 dots: 8 characters
  - Character font 5 x 10 dots: 4 characters
- 4-bit or 8-bit MPU interfaces
- Direct driver for LCD: 16 COMs x 80 SEGs
- Duty factor (selected by program):
  - 1/8 duty: 1 line of 5 x 8 dots
  - 1/11 duty: 1 line of 5 x 10 dots
  - 1/16 duty: 2 lines of 5 x 8 dots / line
- Built-in power on automatic reset circuit
- Built-in oscillator circuit (with external resistor)
- Support external clock operation
- Low Power Consumption
- Package form: bare chip available

## 3. ORDERING INFORMATION

| Product Number | Package Type |
|---|---|
| SPLC783A-NnnV-C | Chip form |
| SPLC783A-NnnV-FL111 | Lead Free Package form - LQFP 128 |
| SPLC783A-NnnV-HL111 | Green Package form - LQFP 128 |
| SPLC783A-NnnV-PL111 | Package form - LQFP 128 |

**Note1:** Code number is assigned for customer.
**Note2:** Code number (N = A - Z or 0 - 9, nn = 00 - 99); version (V = A - Z).

## 4. BLOCK DIAGRAM



## 5. SIGNAL DESCRIPTIONS

| Mnemonic | PIN No. | Type | Description |
|---|---|---|---|
| VDD | 49 | I | Power input |
| VSS | 34 | I | Ground |
| OSC1<br>OSC2 | 36<br>35 | - | Both OSC1 and OSC2 are connected to resistor for internal oscillator circuit. For external clock operation, the clock is input to OSC1. |
| V1 - V5 | 37 - 41 | I | Supply voltage for LCD driving. |
| E | 48 | I | A start signal for reading or writing data. |
| R/W | 47 | I | A signal for selecting read or write actions.<br>1: Read, 0: Write. |
| RS | 46 | I | A signal for selecting registers.<br>1: Data Register (for read and write)<br>0: Instruction Register (for write),<br>Busy flag - Address Counter (for read). |
| DB0 - DB3 | 50 - 53 | I/O | Low 4-bit data |
| DB4 - DB7 | 54 - 57 | I/O | High 4-bit data |
| CLK1 | 42 | O | Clock to latch serial data D. |
| CLK2 | 43 | O | Clock to shift serial data D. |
| M | 44 | O | Switch signal to convert LCD waveform to AC. |
| D | 45 | O | Sends character pattern data corresponding to each common signal serially.<br>1: Selection, 0: Non-selection. |
| SEG1 - SEG33<br>SEG34 - SEG80 | 33 - 1<br>121 - 75 | O | Segment signals for LCD. |
| COM1 - COM16 | 59 - 74 | O | Common signals for LCD. |
| TEST | 58 | I | TEST pin. This pin must be fixed to VDD or open. |

## 6. FUNCTIONAL DESCRIPTIONS

### 6.1. Oscillator

SPLC783A oscillator supports not only the internal oscillator operation, but also the external clock operation.

### 6.2. Control and Display Instructions

Control and display instructions are described in details as follows:

#### 6.2.1. Clear display

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 |

It clears the entire display and sets Display Data RAM Address 0 in Address Counter.

#### 6.2.2. Return home

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | X |

X: Do not care (0 or 1)

It sets Display Data RAM Address 0 in Address Counter and the display returns to its original position. The cursor or blink goes to the most-left side of the display (to the 1st line if 2 lines are displayed). The contents of the Display Data RAM do not change.

#### 6.2.3. Entry mode set

During writing and reading data, it defines cursor moving direction and shifts the display.

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | I / D | S |

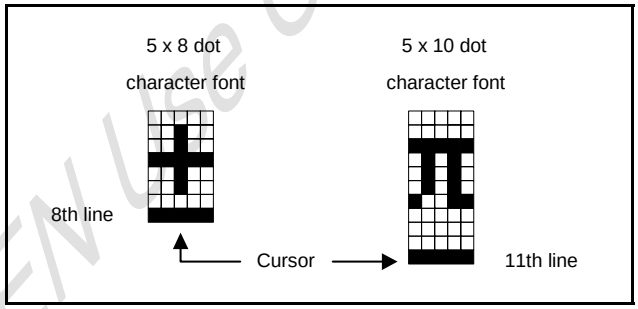
I / D = 1: Increment, I / D = 0: Decrement.
S = 1: The display shift, S = 0: The display does not shift.

| | | |
|---|---|---|
| S = 1 | I / D = 1 | It shifts the display to the left |
| S = 1 | I / D = 0 | It shifts the display to the right |

#### 6.2.4. Display ON/OFF control

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 0 | 0 | 0 | 0 | 0 | 1 | D | C | B |

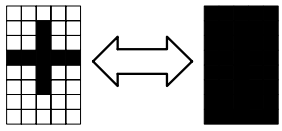
D = 1: Display on, D = 0: Display off
C = 1: Cursor on, C = 0: Cursor off
B = 1: Blinks on, B= 0: Blinks off




#### 6.2.5. Cursor or display shift

Without changing DD RAM data, it moves cursor and shifts display.

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 0 | 0 | 0 | 0 | 1 | S/C | R/L | X | X |



Blink display alternately

| S/C | R/L | Description | Address Counter |
|---|---|---|---|
| 0 | 0 | Shift cursor to the left | AC = AC - 1 |
| 0 | 1 | Shift cursor to the right | AC = AC + 1 |
| 1 | 0 | Shift display to the left. Cursor follows the display shift | AC = AC |
| 1 | 1 | Shift display to the right. Cursor follows the display shift | AC = AC |

### 6.2.6. Function set

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 0 | 0 | 0 | 1 | DL | N | F | X | X |

X: Do not care (0 or 1)
DL: It sets interface data length.
DL = 1: Data transferred with 8-bit length (DB7 - 0).
DL = 0: Data transferred with 4-bit length (DB7 - 4).
It requires two times to accomplish data transferring.
N: It sets the number of the display line.
N = 0: One-line display.
N = 1: Two-line display.
F: It sets the character font.
F = 0: 5 x 8 dots character font.
F = 1: 5 x 10 dots character font.

| N | F | No. of Display Lines | Character Font | Duty Factor |
|---|---|---|---|---|
| 0 | 0 | 1 | 5 x 8 dots | 1 / 8 |
| 0 | 1 | 1 | 5 x 10 dots | 1 / 11 |
| 1 | X | 2 | 5 x 8 dots | 1 / 16 |

It cannot display two lines with 5 x 10 dots character font.

### 6.2.7. Set character generator RAM address

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 0 | 0 | 1 | a | a | a | a | a | a |

It sets Character Generator RAM Address (aaaaaa)2 to the Address Counter.

Character Generator RAM data can be read or written after this setting.

### 6.2.8. Set display data RAM address

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 0 | 1 | a | a | a | a | a | a | a |

It sets Display Data RAM Address $(aaaaaaa)_2$ to the Address Counter.

Display data RAM can be read or written after this setting.

In one-line display (N = 0),

$(aaaaaaa)_2$: $(00)_{16}$ - $(4F)_{16}$.

In two-line display (N = 1),

$(aaaaaaa)_2$: $(00)_{16}$ - $(27)_{16}$ for the first line,

$(aaaaaaa)_2$: $(40)_{16}$ - $(67)_{16}$ for the second line.

### 6.2.9. Read busy flag and address

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 0 | 1 | BF | a | a | a | a | a | a | a |

When BF = 1, it indicates the system is busy now and it will not accept any instruction until not busy (BF = 0). At the same time, the content of Address Counter $(aaaaaaa)_2$ is read.

### 6.2.10. Write data to character generator RAM or display data RAM

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 1 | 0 | d | d | d | d | d | d | d | d |

It writes data $(dddddddd)_2$ to character generator RAM or display data RAM.

### 6.2.11. Read data from character generator RAM or display data RAM

| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
|---|---|---|---|---|---|---|---|---|---|---|
| Code | 1 | 1 | d | d | d | d | d | d | d | d |

It reads data $(dddddddd)_2$ from character generator RAM or display data RAM.

To read data correctly, do the following:

1). The address of the Character Generator RAM or Display Data RAM or shift the cursor instruction.

2). The " Read " instruction.

### 6.3. Instruction Table

| Instruction | Instruction Code | | | | | | | | | | Description | Execution time | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 | | Fosc= 190KHz | Fosc= 270KHz | Fosc= 350KHz |
| Clear Display | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | Write "20H" to DDRAM and set DDRAM address to "00H" from AC | 2.16ms | 1.52ms | 1.18ms |
| Return Home | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | - | Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed. | 2.16ms | 1.52ms | 1.18ms |
| Entry Mode Set | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | I/D | S | Assign cursor moving direction and enable the shift of entire display | 53μs | 38μs | 29μs |
| Display ON/ OFF Control | 0 | 0 | 0 | 0 | 0 | 0 | 1 | D | C | B | Set display (D), cursor(C), and blinking of cursor(B) on/off control bit. | 53μs | 38μs | 29μs |
| Cursor or Display Shift | 0 | 0 | 0 | 0 | 0 | 1 | S/C | R/L | - | - | Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data. | 53μs | 38μs | 29μs |
| Function Set | 0 | 0 | 0 | 0 | 1 | DL | N | F | - | - | Set interface data length (DL: 8-bit/4-bit), numbers of display line (N: 2-line/1-line) and, display font type (F:5x10 dots/5x8 dots) | 53μs | 38μs | 29μs |
| Set CGRAM Address | 0 | 0 | 0 | 1 | AC5 | AC4 | AC3 | AC2 | AC1 | AC0 | Set CGRAM address in address counter. | 53μs | 38μs | 29μs |
| Set DDRAM Address | 0 | 0 | 1 | AC6 | AC5 | AC4 | AC3 | AC2 | AC1 | AC0 | Set DDRAM address in address counter | 53μs | 38μs | 29μs |
| Read Busy Flag and Address Counter | 0 | 1 | BF | AC6 | AC5 | AC4 | AC3 | AC2 | AC1 | AC0 | Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read. | | | |
| Write Data to RAM | 1 | 0 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Write data into internal RAM (DDRAM/CGRAM). | 53μs | 38μs | 29μs |
| Read Data from RAM | 1 | 1 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Read data from internal RAM (DDRAM/CGRAM). | 53μs | 38μs | 29μs |

**Note:** "-": don't care

### 6.4. 8-Bit Operation and 8-Digit 1-Line Display (Using Internal Reset)

| No. | Instruction | Display | Operation |
|---|---|---|---|
| 1 | Power on. (SPLC783A starts initializing) | | Power on reset. No display. |
| 2 | Function set<br>RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0<br>0 0 0 0 1 1 0 0 X X | | Set to 8-bit operation and select 1-line display line and character font. |
| 3 | Display on / off control<br>0 0 0 0 0 0 1 1 1 0 | _ | Display on.<br>Cursor appear. |
| 4 | Entry mode set<br>0 0 0 0 0 0 0 1 1 0 | _ | Increase address by one.<br>It will shift the cursor to the right when writing to the DD RAM/CG RAM.<br>Now the display has no shift. |
| 5 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 1 0 1 1 1 | W_ | Write " W ".<br>The cursor is incremented by one and shifted to the right. |
| 6 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 0 0 1 0 1 | WE_ | Write " E ".<br>The cursor is incremented by one and shifted to the right. |
| 7 | : | : | |
| 8 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 0 0 1 0 1 | WELCOME_ | Write " E ".<br>The cursor is incremented by one and shifted to the right. |
| 9 | Entry mode set<br>0 0 0 0 0 0 0 1 1 1 | WELCOME_ | Set mode for display shift when writing |
| 10 | Write data to CG RAM / DD RAM<br>1 0 0 0 1 0 0 0 0 0 | ELCOME _ | Write " "(space).<br>The cursor is incremented by one and shifted to the right. |
| 11 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 0 0 0 1 1 | LCOME C_ | Write " C ".<br>The cursor is incremented by one and shifted to the right. |
| 12 | : | : | |
| 13 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 1 1 0 0 1 | COMPAMY_ | Write " Y ".<br>The cursor is incremented by one and shifted to the right. |
| 14 | Cursor or display shift<br>0 0 0 0 0 1 0 0 X X | COMPAMY_ | Only shift the cursor's position to the left (Y). |
| 15 | Cursor or display shift<br>0 0 0 0 0 1 0 0 X X | COMPAMY_ | Only shift the cursor's position to the left (M). |
| 16 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 0 1 1 1 0 | OMPANY_ | Write " N ".<br>The display moves to the left. |
| 17 | Cursor or display shift<br>0 0 0 0 0 1 1 1 X X | COMPAMY_ | Shift the display and the cursor's position to the right. |
| 18 | Cursor or display shift<br>0 0 0 0 0 1 0 1 X X | OMPANY_ | Shift the display and the cursor's position to the right. |
| 19 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 0 0 0 0 0 | COMPAMY_ | Write " " (space).<br>The cursor is incremented by one and shifted to the right. |
| 20 | : | : | : |
| 21 | Return home<br>0 0 0 0 0 0 0 0 1 0 | WELCOME_ | Both the display and the cursor return to the original position (address 0). |

### 6.5. 4-Bit Operation and 8-Digit 1-Line Display (Using Internal Reset)

| No. | Instruction | Display | Operation |
|---|---|---|---|
| 1 | Power on.<br>(SPLC783A starts initializing) | | Power on reset. No display. |
| 2 | Function set<br>RS R/W DB7 DB6 DB5 DB4<br>0 0 0 0 1 0 | | Set to 4-bit operation. |
| 3 | 0 0 0 0 1 0<br>0 0 0 0 X X | | Set to 4-bit operation and select 1-line display line and character font. |
| 4 | 0 0 0 0 0 0<br>0 0 1 1 1 0 | _ | Display on.<br>Cursor appears. |
| 5 | 0 0 0 0 0 0<br>0 0 0 1 1 0 | _ | Increase address by one.<br>It will shift the cursor to the right when writing to the DD RAM / CG RAM.<br>Now the display has no shift. |
| 6 | 1 0 0 1 0 1<br>1 0 0 1 1 1 | W_ | Write " W ".<br>The cursor is incremented by one and shifted to the right. |

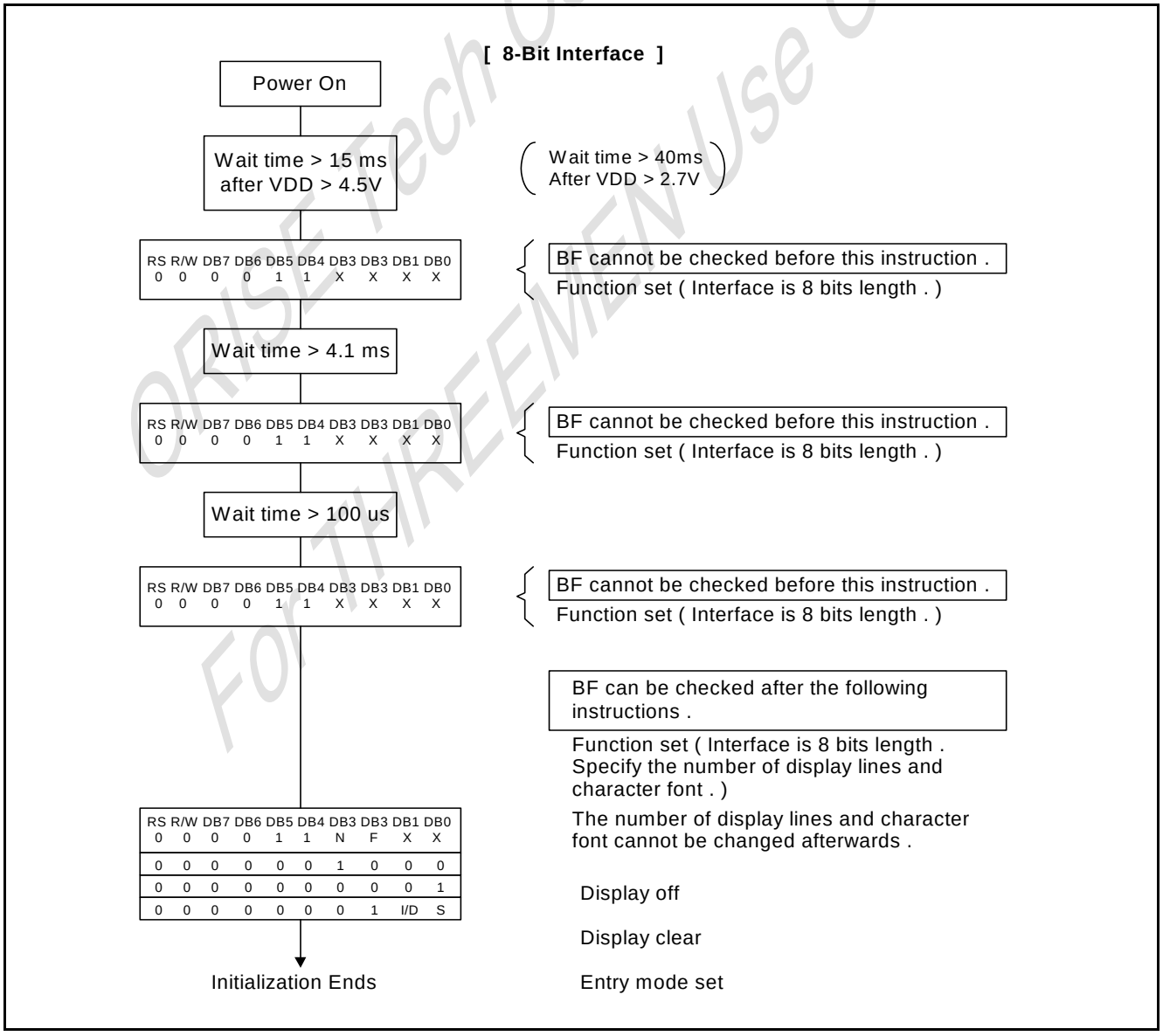
### 6.6. 8-Bit Operation and 8-Digit 2-Line Display (Using Internal Reset)

| No. | Instruction | Display | Operation |
|---|---|---|---|
| 1 | Power on.<br>(SPLC783A starts initializing) | | Power on reset. No display. |
| 2 | Function set<br>RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0<br>0 0 0 0 1 1 1 0 X X | | Set to 8-bit operation and select 2-line display line and 5 x 8 dot character font. |
| 3 | Display on / off control<br>0 0 0 0 0 0 1 1 1 0 | _ | Display on.<br>Cursor appear. |
| 4 | Entry mode set<br>0 0 0 0 0 0 0 1 1 0 | _ | Increase address by one.<br>It will shift the cursor to the right when writing to the DD RAM / CG RAM.<br>Now the display has no shift. |
| 5 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 1 0 1 1 1 | W_ | Write " W ".<br>The cursor is incremented by one and shifted to the right. |
| 6 | : | : | : |
| 7 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 0 0 1 0 1 | WELCOME_ | Write " E ".<br>The cursor is incremented by one and shifted to the right. |
| 8 | Set DD RAM address<br>0 0 1 1 0 0 0 0 0 0 | WELCOME<br>_ | It sets DD RAM's address.<br>The cursor is moved to the beginning position of the 2nd line. |
| 9 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 1 0 1 0 0 | WELCOME<br>T_ | Write " T ".<br>The cursor is incremented by one and shifted to the right. |
| 10 | : | : | : |
| 11 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 1 0 1 0 0 | WELCOME<br>TO PART_ | Write " T ".<br>The cursor is incremented by one and shifted to the right. |

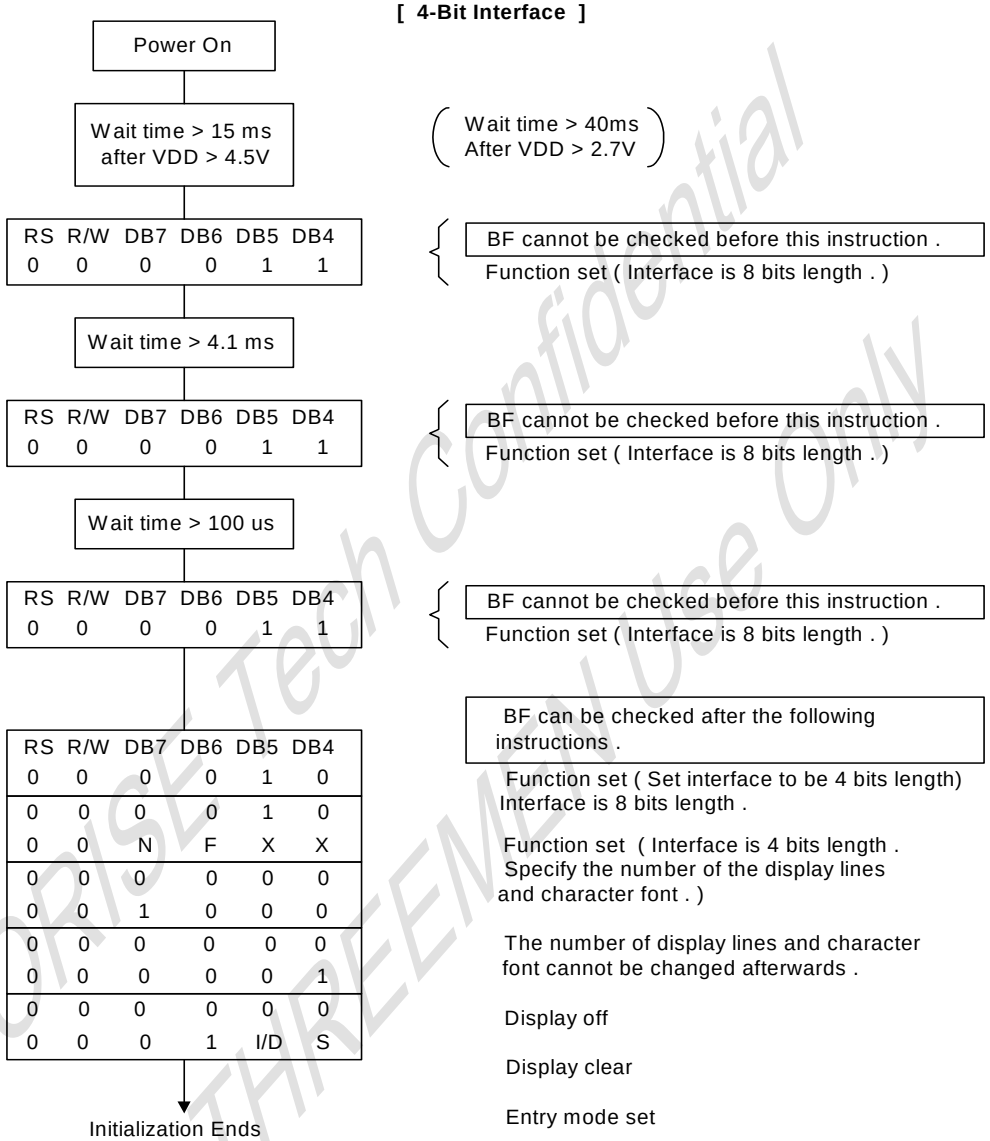
| No. | Instruction | Display | Operation |
|---|---|---|---|
| 12 | Entry mode set<br>0 0 0 0 0 0 0 1 1 1 | WELCOME<br>TO PART_ | When writing, it sets mode for the display shift. |
| 13 | Write data to CG RAM / DD RAM<br>1 0 0 1 0 1 1 0 0 1 | ELCOME<br>O PARTY_ | Write " Y ".<br>The cursor is incremented by one and shifted to the right. |
| 14 | : | : | : |
| 15 | Return home<br>0 0 0 0 0 0 0 0 1 0 | WELCOME<br>TO PARTY | Both the display and the cursor return to the original position (address 0). |

### 6.7. RESET Function

At power on, SPLC783A starts the internal auto-reset circuit and executes the initial instructions. The initial procedures are shown as follows:

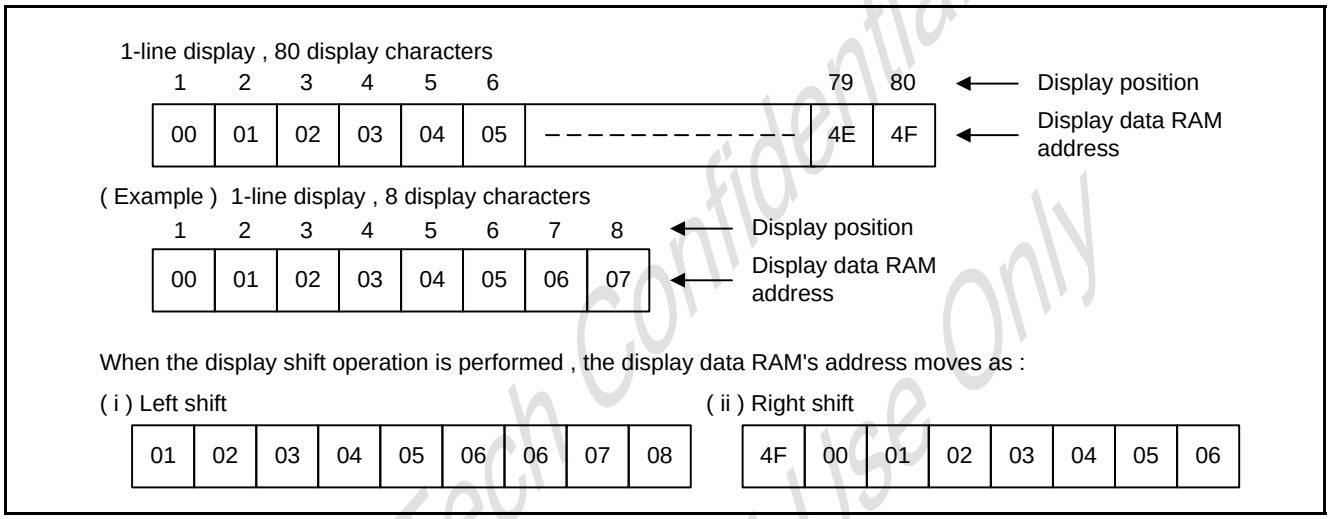


**[ 4-Bit Interface ]**



### 6.8. Display Data RAM (DD RAM)

The 80-bit DD RAM is normally used for storing display data. Those DD RAM not used for display data can be used as general data RAM. Its address is configured in the Address Counter. The relationships between Display Data RAM Address and LCD′s position are depicted as follows.




### 6.9. Timing Generation Circuit

The timing generating circuit is able to generate timing signals to the internal circuits. In order to prevent the internal timing interface, the MPU access timing and the RAM access timing are generated independently.

### 6.10. LCD Driver Circuit

Total of 16 commons and 80 segments signal drivers are valid in the LCD driver circuit. When a program specifies the character fonts and line numbers, the corresponding common signals output drive-waveforms and the others still output unselected waveforms.

### 6.11. Character Generator ROM (CG ROM)

Using 8-bit character code, the character generator ROM generates 5 x 8 dots or 5 x 10 dots character patterns. It also can generate 192's 5 x 8 dots character patterns and 64's 5 x 10 dots character patterns.

### 6.12. Character Generator RAM (CG RAM)

Users can easily change the character patterns in the character generator RAM through program. It can be written to 5 x 8 dots, 8-character patterns or 5 x 10 dots for 4-character patterns.

The following diagram shows the SPLC783A character patterns:

Correspondence between Character Codes and Character Patterns.

| Lower 4-bit (D0 to D3) of Character Code (Hexadecimal) | Higher 4-bit (D4 to D7) of Character Code (Hexadecimal) | | | | | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | 0 | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | A | B | C | D | E | F |
| 0 | CG RAM (1) | | | | | | | | | | | | | | | |
| 1 | CG RAM (2) | | | | | | | | | | | | | | | |
| 2 | CG RAM (3) | | | | | | | | | | | | | | | |
| 3 | CG RAM (4) | | | | | | | | | | | | | | | |
| 4 | CG RAM (5) | | | | | | | | | | | | | | | |
| 5 | CG RAM (6) | | | | | | | | | | | | | | | |
| 6 | CG RAM (7) | | | | | | | | | | | | | | | |
| 7 | CG RAM (8) | | | | | | | | | | | | | | | |
| 8 | CG RAM (1) | | | | | | | | | | | | | | | |
| 9 | CG RAM (2) | | | | | | | | | | | | | | | |
| A | CG RAM (3) | | | | | | | | | | | | | | | |
| B | CG RAM (4) | | | | | | | | | | | | | | | |
| C | CG RAM (5) | | | | | | | | | | | | | | | |
| D | CG RAM (6) | | | | | | | | | | | | | | | |
| E | CG RAM (7) | | | | | | | | | | | | | | | |
| F | CG RAM (8) | | | | | | | | | | | | | | | |

The relationships between Character Generator RAM Addresses, Character Generator RAM Data (character patterns), and Character Codes are depicted as follows:

**1. 5 x 8 dot character patterns**

| Character Code ( DD RAM Data ) | | | | | | | | CG RAM Address | | | | | | Character Patterns ( CG RAM Data ) | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| b7 | b6 | b5 | b4 | b3 | b2 | b1 | b0 | b5 | b4 | b3 | b2 | b1 | b0 | | b7 | b6 | b5 | b4 | b3 | b2 | b1 | b0 |
| 0 | 0 | 0 | 0 | X | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | | X | X | X | 1 | 1 | 1 | 1 | 1 |
| | | | | | | | | | | | 0 | 0 | 1 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 0 | 1 | 0 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 0 | 1 | 1 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 1 | 0 | 0 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 1 | 0 | 1 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 1 | 1 | 0 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 1 | 1 | 1 | | | | | 0 | 0 | 0 | 0 | 0 |
| 0 | 0 | 0 | 0 | X | 0 | 0 | 1 | 0 | 0 | 1 | 0 | 0 | 0 | | X | X | X | 0 | 1 | 1 | 1 | 0 |
| | | | | | | | | | | | 0 | 0 | 1 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 0 | 1 | 0 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 0 | 1 | 1 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 1 | 0 | 0 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 1 | 0 | 1 | | | | | 0 | 0 | 1 | 0 | 0 |
| | | | | | | | | | | | 1 | 1 | 0 | | | | | 0 | 1 | 1 | 1 | 0 |
| | | | | | | | | | | | 1 | 1 | 1 | | | | | 0 | 0 | 0 | 0 | 0 |

Character Pattern Example (1)

Cursor Position

Character Pattern Example (2)

**Note1:** ▨ It means that the bit0~2 of the character code correspond to the bit3~5 of the CG RAM address.

**Note2:** ▤ These areas are not used for display, but can be used for the general data RAM.

**Note3:** When all of the bit4-7 of the character code are 0, CG RAM character patterns are selected.

**Note4:** " 1 ": Selected , " 0 " : No selected , " X " : Do not care (0 or 1).

**Note5:** For example (1), set character code (b2 = b1 = b0 = 0, b3 = 0 or 1, b7-b4 = 0) to display " T ". That means character code (00) 16,and (08) 16 can display " T " character.

**Note6:** The bits 0-2 of the character code RAM is the character pattern line position. The 8th line is the cursor position and display is formed by logical OR with the cursor.

**2). 5 X 10 dot character patterns**

| Character Code ( DD RAM Data ) | | | | | | | | CG RAM Address | | | | | | Character Patterns ( CG RAM Data ) | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| b7 | b6 | b5 | b4 | b3 | b2 | b1 | b0 | b5 | b4 | b3 | b2 | b1 | b0 | b7 | b6 | b5 | b4 | b3 | b2 | b1 | b0 | |
| 0 | 0 | 0 | 0 | X | 0 | 0 | X | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | 1 | 0 | 0 | 0 | 1 | Character Pattern Example (1) |
| | | | | | | | | | | 0 | 0 | 0 | 1 | - | - | - | 1 | 0 | 0 | 0 | 1 | |
| | | | | | | | | | | 0 | 0 | 1 | 0 | - | - | - | 1 | 0 | 0 | 0 | 1 | |
| | | | | | | | | | | 0 | 0 | 1 | 1 | - | - | - | 1 | 0 | 0 | 0 | 1 | |
| | | | | | | | | | | 0 | 1 | 0 | 0 | - | - | - | 1 | 0 | 0 | 0 | 1 | |
| | | | | | | | | | | 0 | 1 | 0 | 1 | X | X | X | 1 | 0 | 0 | 0 | 1 | |
| | | | | | | | | | | 0 | 1 | 1 | 0 | - | - | - | 1 | 0 | 0 | 0 | 1 | |
| | | | | | | | | | | 0 | 1 | 1 | 1 | - | - | - | 1 | 0 | 0 | 0 | 1 | |
| | | | | | | | | | | 1 | 0 | 0 | 0 | - | - | - | 1 | 0 | 0 | 0 | 1 | |
| | | | | | | | | | | 1 | 0 | 0 | 1 | - | - | - | 1 | 1 | 1 | 1 | 1 | Cursor Position |
| | | | | | | | | | | 1 | 0 | 1 | 0 | - | - | - | 0 | 0 | 0 | 0 | 0 | ← |
| | | | | | | | | | | 1 | 0 | 1 | 1 | - | - | - | - | - | - | - | - | |
| | | | | | | | | | | 1 | 1 | 0 | 0 | - | - | - | - | - | - | - | - | |
| | | | | | | | | | | 1 | 1 | 0 | 1 | X | X | X | X | X | X | X | X | |
| | | | | | | | | | | 1 | 1 | 1 | 0 | - | - | - | - | - | - | - | - | |
| | | | | | | | | | | 1 | 1 | 1 | 1 | - | - | - | - | - | - | - | - | |



**Note1:** ▨ It means that the bit1~2 of the character code correspond to the bit4~5 of the CG RAM address.

**Note2:** ▤ These areas are not used for display, but can be used for the general data RAM.

**Note3:** When all of the bit4-7 of the character code are 0, CG RAM character patterns are selected.

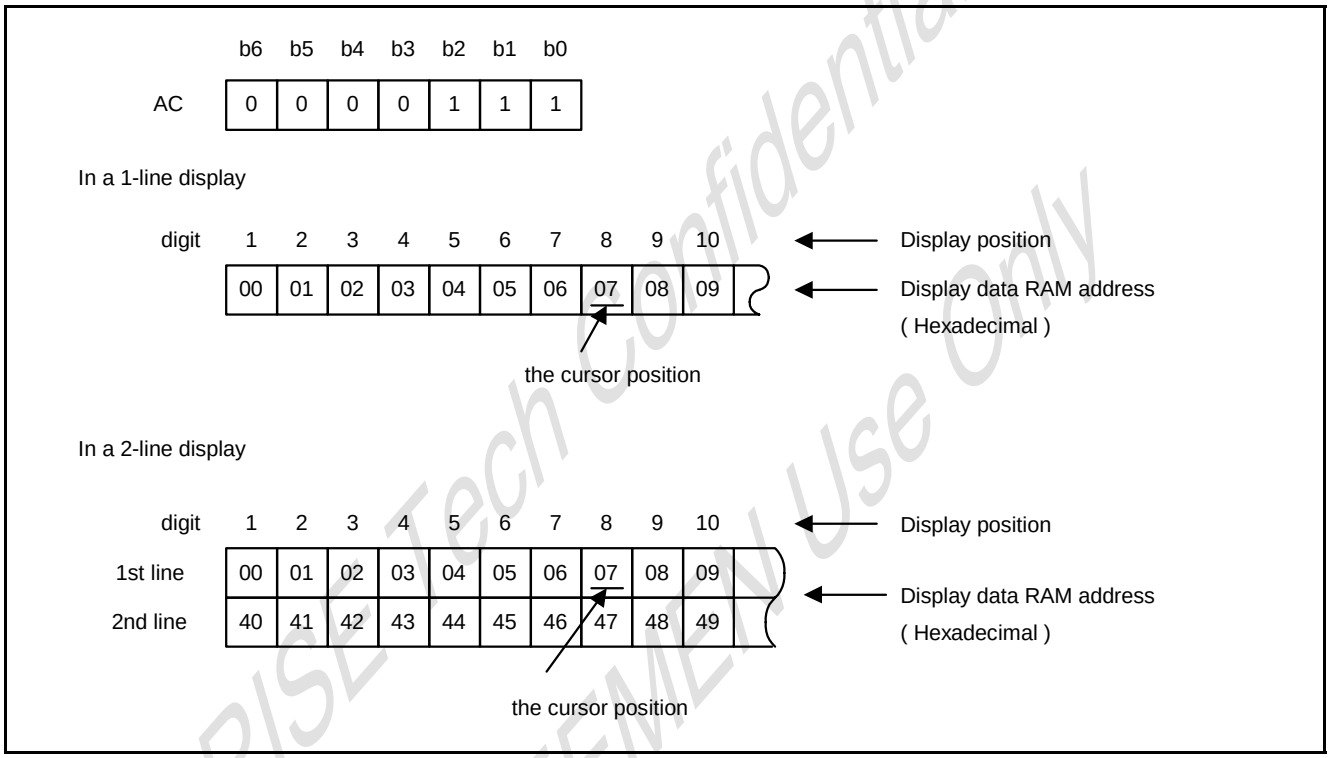
**Note4:** " 1 ": Selected, " 0 ": No selected, " X ": Do not care (0 or 1).

**Note5:** For example (1), set character code (b2 = b1 = 0, b3 = b0 = 0 or 1, b7-b4 = 0) to display " U ". That means all of the character codes (00) 16, (01) 16, (08) 16,and (09) 16 can display " U " character.

**Note6:** The bits 0-3 of the character code RAM is the character pattern line position. The 11th line is the cursor position and display is formed by logical OR with the cursor.

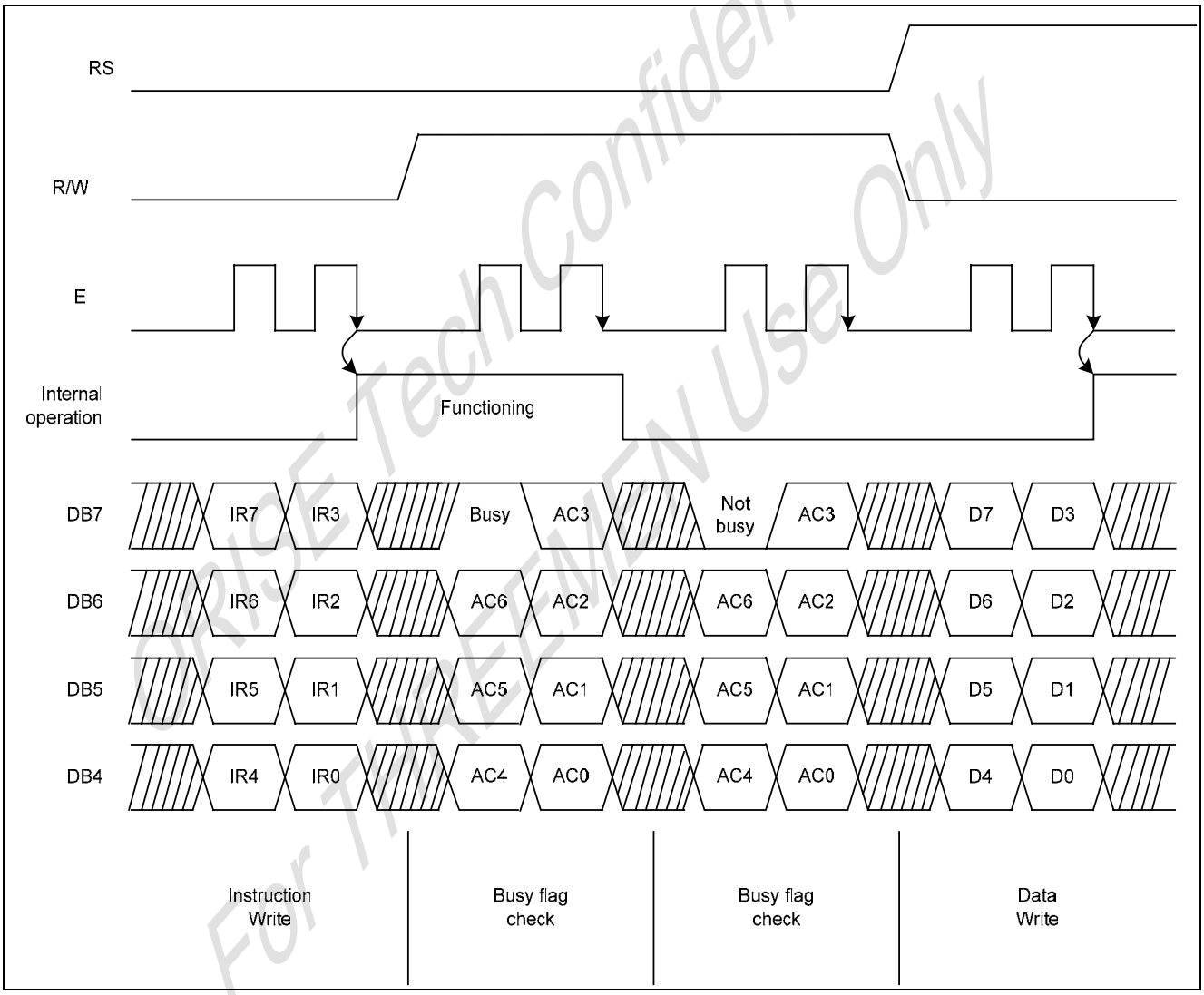
### 6.13. Cursor/Blink Control Circuit

This circuit generates the cursor or blink in the cursor / blink control circuit. The cursor or the blink appears in the digit at the Display Data RAM Address defined in the Address Counter. When the Address Counter is (07) 16, the cursor position is shown as belows:

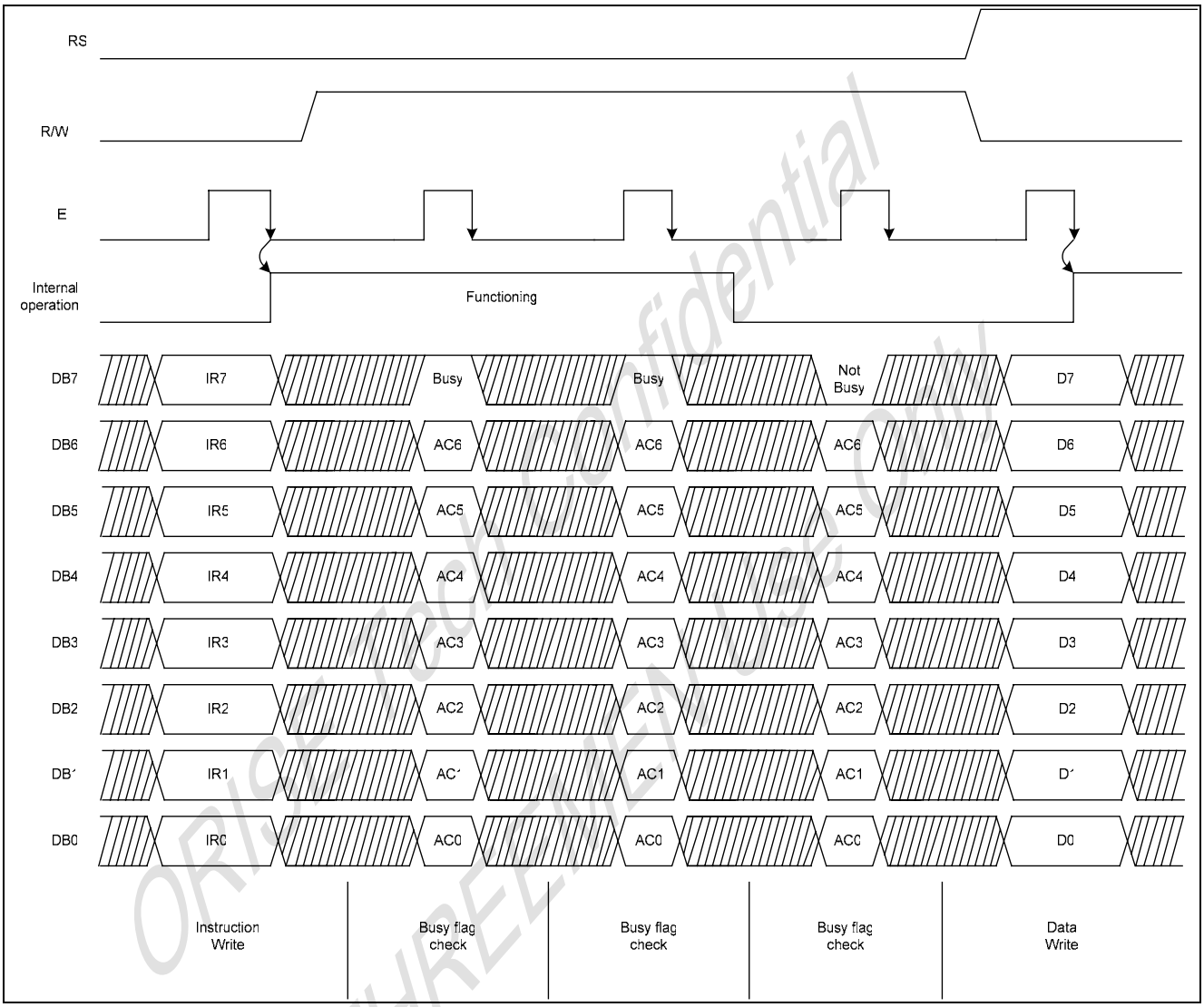


### 6.14. Interfacing to MPU

There are two types of data operations: 4-bit and 8-bit operations. Using 4-bit MPU, the interfacing 4-bit data is transferred by 4-busline (DB4 to DB7). Thus, DB0 to DB3 bus lines are not used. Using 4-bit MPU to interface 8-bit data requires two times transferring. First, the higher 4-bit data is transferred by 4-busline (for 8-bit operation, DB7 to DB4). Secondly, the lower 4-bit data is transferred by 4-busline (for 8-bit operation, DB3 to DB0). For 8-bit MPU, the 8-bit data is transferred by 8-buslines (DB0 to DB7).




Example of 4-bit Data Transfer Timing Sequence



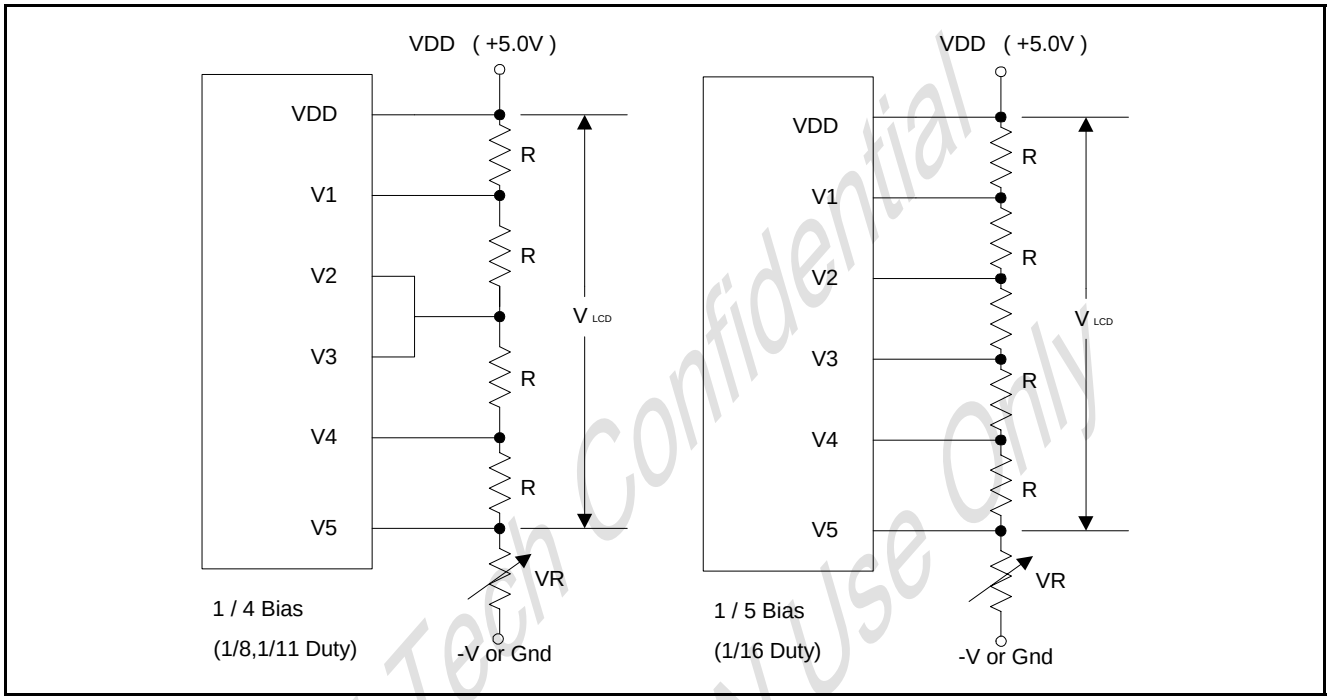

Example of 8-bit Data Transfer Timing Sequence

### 6.15. Supply Voltage for LCD Drive

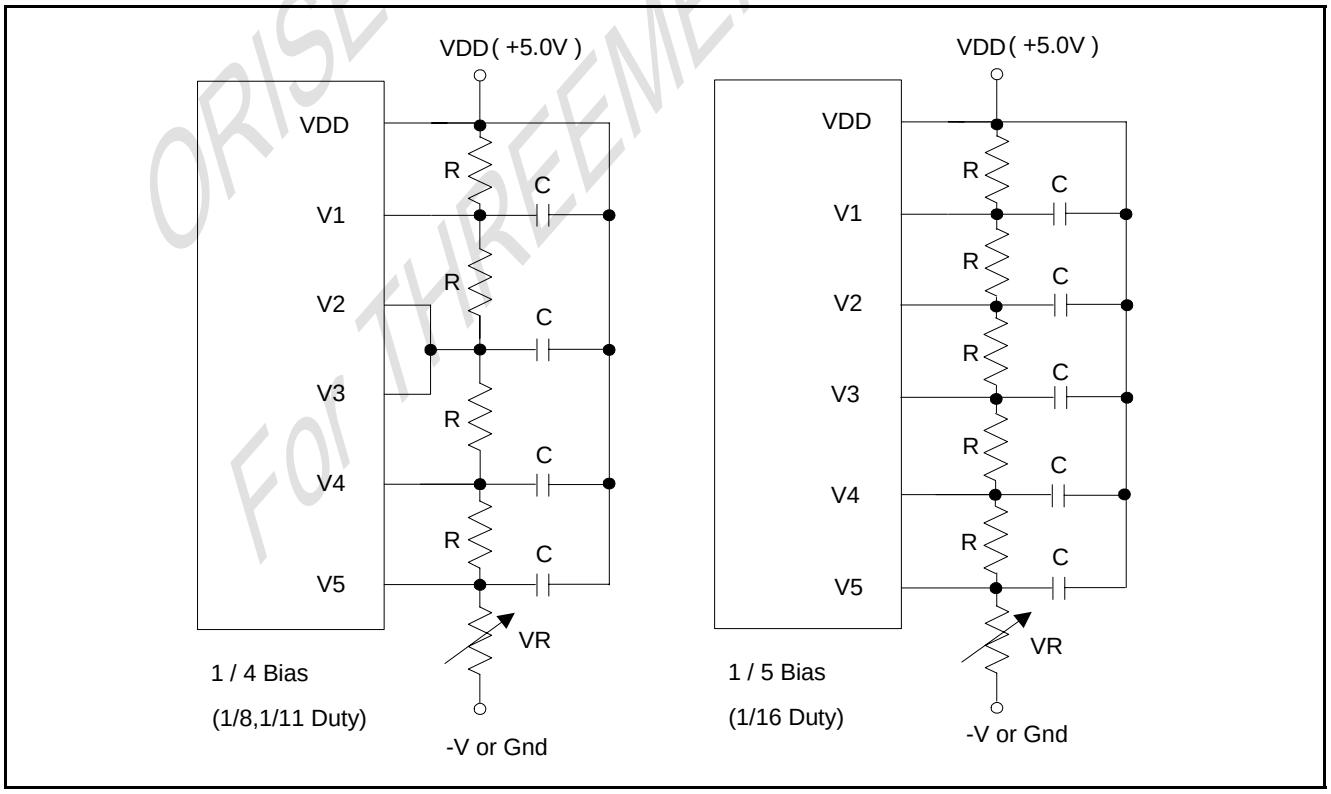
Different voltages can be supplied to SPLC783A's pins (V5 - 1) for obtaining LCD drive-waveform. The relationships between bias, duty factor and supply voltages are shown as belows:

| Supply Voltage \ Duty Factor | 1/8, 1/11 | 1/16 |
|---|---|---|
| | 1/4 | 1/5 |
| V1 | VDD – 1/4 $V_{LCD}$ | VDD – 1/5 $V_{LCD}$ |
| V2 | VDD – 1/2 $V_{LCD}$ | VDD – 2/5 $V_{LCD}$ |
| V3 | VDD – 1/2 $V_{LCD}$ | VDD – 3/5 $V_{LCD}$ |
| V4 | VDD – 3/4 $V_{LCD}$ | VDD – 4/5 $V_{LCD}$ |
| V5 | VDD – $V_{LCD}$ | VDD – $V_{LCD}$ |

### 6.15.1. The power connections for LCD (1/4 Bias, 1/5 Bias) are shown belows:




The bypass-capacitor improves the LCD display quality.



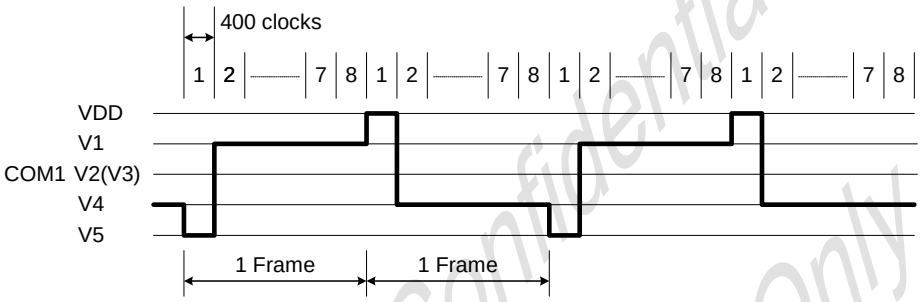

The bias voltage must have the following relations:

VDD > V1 > V2 ≧ V3 > V4 > V5.

### 6.15.2. The relationship between LCD frame's frequency and oscillator's frequency.

(Assume the oscillation frequency is 250KHz, 1 clock cycle time = 4.0μs)

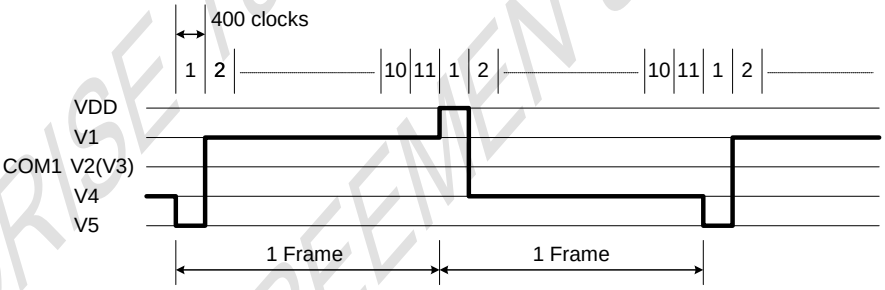
#### 6.15.2.1. 1/8 duty, TYPE-B waveform




1 frame = 4(μs) x 400 x 8 = 12800(μs) = 12.8ms

$$\text{Frame frequency} = \frac{1}{12.8(\text{ms})} = 78.1(\text{Hz})$$

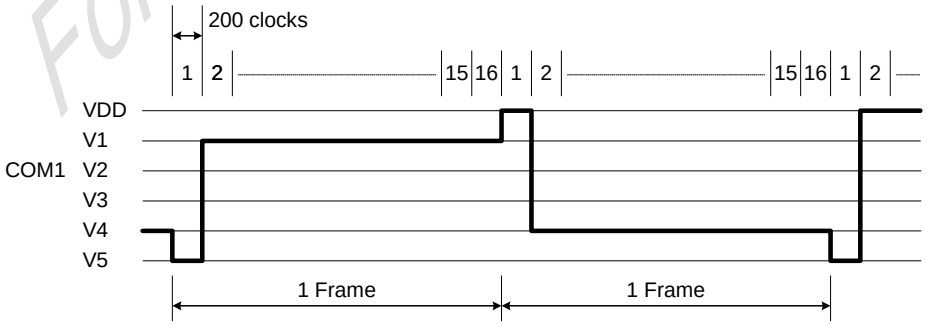
#### 6.15.2.2. 1/11 duty, TYPE-B waveform




1 frame = 4(μs) x 400 x 11 = 17600(μs) = 17.6ms

$$\text{Frame frequency} = \frac{1}{17.6(\text{ms})} = 56.8(\text{Hz})$$

#### 6.15.2.3. 1/16 duty, TYPE-B waveform




1 frame = 4(μs) x 200 x 16 = 12800(μs) = 12.8ms

$$\text{Frame frequency} = \frac{1}{12.8(\text{ms})} = 78.1(\text{Hz})$$

### 6.16. REGISTER --- IR (Instruction Register) and DR (Data Register)

SPLC783A contains two 8-bit registers: Instruction Register (IR) and Data Register (DR). Using combinations of the RS pin and the R/W pin selects the IR and DR, see below:

| RS | R/W | Operation |
|---|---|---|
| 0 | 0 | IR write (Display clear, etc.) |
| 0 | 1 | Read busy flag (DB7) and Address Counter (DB0 - DB6) |
| 1 | 0 | DR write (DR to Display data RAM or Character generator RAM) |
| 1 | 1 | DR read (Display data RAM or Character generator RAM to DR) |

The IR can be written by MPU, but it cannot be read by MPU.

### 6.17. Busy Flag (BF)

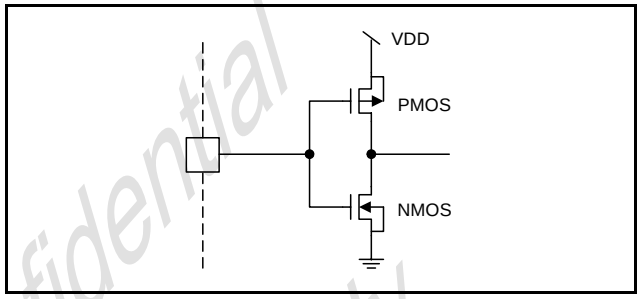
When RS = 0 and R/W = 1, the busy flag is output to DB7. As the busy flag =1, SPLC783A is in busy state and does not accept any instruction until the busy flag = 0.

### 6.18. Address Counter (AC)

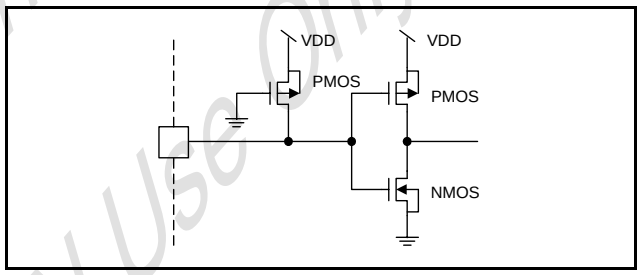
The Address Counter assigns addresses to Display Data RAM and Character Generator RAM. When an instruction for address is written in IR, the address information is sent from IR to AC. After writing to/reading from Display Data RAM or Character Generator RAM, AC is automatically incremented by one (or decremented by one). The contents of AC are output to DB0 - DB6 when RS = 0 and R/W = 1.

### 6.19. I/O Port Configuration

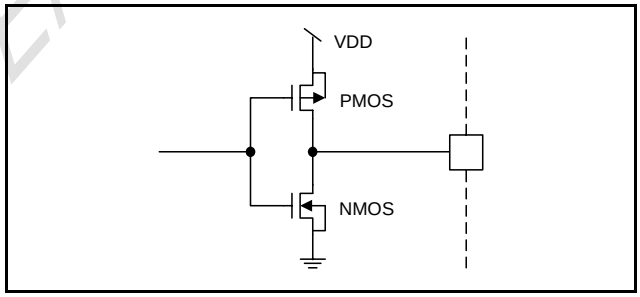
#### 6.19.1. Input port: E



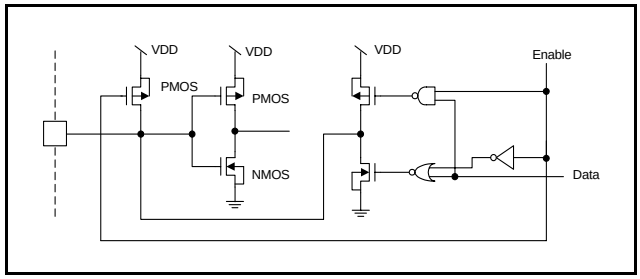

#### 6.19.2. Input port: R / W, RS




#### 6.19.3. Output port: CLK1, CLK2, M, D




#### 6.19.4. Input / Output port: DB7 - 0



## 7. ELECTRICAL SPECIFICATIONS

### 7.1. Absolute Maximum Ratings

| Characteristics | Symbol | Ratings |
|---|---|---|
| Operating Voltage | VDD | -0.3V to +7.0V |
| Driver Supply Voltage | $V_{LCD}$ | VDD - 12V to VDD + 0.3V |
| Input Voltage Range | $V_{IN}$ | -0.3V to VDD + 0.3V |
| Operating Temperature | $T_A$ | -30℃ to +80℃ |
| Storage Temperature | $T_{STO}$ | -55℃ to +125℃ |

**Note:** Stresses beyond those given in the Absolute Maximum Rating table may cause operational errors or damage to the device. For normal operational conditions see AC/DC Electrical Characteristics.

### 7.2. DC Characteristics (VDD = 2.7V to 4.5V, $T_A$ = 25℃)

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| Operating Current | $I_{DD}$ | - | 0.2 | 0.4 | mA | External clock (Note) |
| Input High Voltage | $V_{IH1}$ | 0.7VDD | - | VDD | V | Pins:(E, RS, R/W, DB0 - DB7) |
| Input Low Voltage | $V_{IL1}$ | -0.3 | - | 0.4 | V | |
| Input High Voltage | $V_{IH2}$ | 0.7VDD | - | VDD | V | Pin OSC1 |
| Input Low Voltage | $V_{IL2}$ | -0.2 | - | 0.2VDD | V | |
| Input High Current | $I_{IH}$ | -1.0 | - | 1.0 | μA | Pins: (RS, R/W, DB0 - DB7) |
| Input Low Current | $I_{IL}$ | -5.0 | -15 | -30 | μA | VDD = 3.0V |
| Output High Voltage (TTL) | $V_{OH1}$ | 2.0 | - | - | V | $I_{OH}$ = - 0.1mA Pins: DB0 - DB7 |
| Output Low Voltage (TTL) | $V_{OL1}$ | - | - | 0.2VDD | V | $I_{OL}$ = 0.1mA Pins: DB0 - DB7 |
| Output High Voltage (CMOS) | $V_{OH2}$ | 0.8VDD | - | - | V | $I_{OH}$ = - 40μA, Pins: CLK1, CLK2, M, D |
| Output Low Voltage (CMOS) | $V_{OL2}$ | - | - | 0.2VDD | V | $I_{OL}$ = 40μA, Pins: CLK1, CLK2, M, D |
| Driver ON Resistance (COM) | $R_{COM}$ | - | - | 10 | KΩ | $I_O$ = ±50μA, $V_{LCD}$ = 4.0V Pins: COM1 - COM16 |
| Driver ON Resistance (SEG) | $R_{SEG}$ | - | - | 15 | KΩ | $I_O$ = ±50μA, $V_{LCD}$ = 4.0V Pins: SEG1 - SEG80 |
| LCD Voltage | $V_{LCD}$ | 3.0 | - | 11 | V | VDD-V5, 1/4 bias or 1/5 bias |

**Note:** $F_{OSC}$ = 270KHz, VDD = 3.0V, pin E = "L", RS, R/W, DB0 - DB7 are open, all outputs are no loads.

### 7.3. AC Characteristics (VDD = 2.7V to 4.5V, $T_A$ = 25℃)

#### 7.3.1. Internal clock operation

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| OSC Frequency | $F_{OSC1}$ | 190 | 270 | 350 | KHz | VDD = 3.0V, Rf = 75KΩ±2% |

#### 7.3.2. External clock operation

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| External Frequency | $F_{OSC2}$ | 125 | 250 | 350 | KHz | |
| Duty Cycle | | 45 | 50 | 55 | % | |
| Rise/Fall Time | tr, tf | - | - | 0.2 | μs | |

#### 7.3.3. Write mode (Writing data from MPU to SPLC783A)

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| E Cycle Time | $t_C$ | 1400 | - | - | ns | Pin E |
| E Pulse Width | $t_{PW}$ | 400 | - | - | ns | Pin E |
| E Rise/Fall Time | $t_R$, $t_F$ | - | - | 25 | ns | Pin E |
| Address Setup Time | $t_{SP1}$ | 60 | - | - | ns | Pins: RS, R/W, E |
| Address Hold Time | $t_{HD1}$ | 20 | - | - | ns | Pins: RS, R/W, E |
| Data Setup Time | $t_{SP2}$ | 140 | - | - | ns | Pins: DB0 - DB7 |
| Data Hold Time | $t_{HD2}$ | 10 | - | - | ns | Pins: DB0 - DB7 |

#### 7.3.4. Read mode (Reading data from SPLC783A to MPU)

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| E Cycle Time | $t_C$ | 1400 | - | - | ns | Pin E |
| E Pulse Width | $t_W$ | 400 | - | - | ns | Pin E |
| E Rise/Fall Time | $t_R$, $t_F$ | - | - | 25 | ns | Pin E |
| Address Setup Time | $t_{SP1}$ | 60 | - | - | ns | Pins: RS, R/W, E |
| Address Hold Time | $t_{HD1}$ | 20 | - | - | ns | Pins: RS, R/W, E |
| Data Output Delay Time | $t_D$ | - | - | 360 | ns | Pins: DB0 - DB7 |
| Data hold time | $t_{HD2}$ | 5.0 | - | - | ns | Pin DB0 - DB7 |

### 7.4. DC Characteristics (VDD = 4.5V to 5.5V, $T_A$ = 25℃)

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| Operating Current | $I_{DD}$ | - | 0.4 | 0.6 | mA | External clock (Note) |
| Input High Voltage | $V_{IH1}$ | 2.2 | - | VDD | V | Pins:(E, RS, R/W, DB0 - DB7) |
| Input Low Voltage | $V_{IL1}$ | -0.3 | - | 0.6 | V | |
| Input High Voltage | $V_{IH2}$ | VDD-1 | - | VDD | V | Pin OSC1 |
| Input Low Voltage | $V_{IL2}$ | -0.2 | - | 1.0 | V | Pin OSC1 |
| Input High Current | $I_{IH}$ | -1.0 | - | 1.0 | μA | Pins: (RS, R/W, DB0 - DB7)<br>VDD = 5.0V |
| Input Low Current | $I_{IL}$ | -20 | -50 | -100 | μA | |
| Output High Voltage (TTL) | $V_{OH1}$ | 2.4 | - | VDD | V | $I_{OH}$ = -0.205mA<br>Pins: DB0 - DB7 |
| Output Low Voltage (TTL) | $V_{OL1}$ | - | - | 0.4 | V | $I_{OL}$ = 1.2mA<br>Pins: DB0 - DB7 |
| Output High Voltage (CMOS) | $V_{OH2}$ | 0.9VDD | - | VDD | V | $I_{OH}$ = -40μA,<br>Pins: CLK1, CLK2, M, D |
| Output Low Voltage (CMOS) | $V_{OL2}$ | - | - | 0.1VDD | V | $I_{OL}$ = 40μA, Pins:<br>CLK1, CLK2, M, D |
| Driver ON Resistance (COM) | $R_{COM}$ | - | - | 10K | KΩ | $I_O$ = ±50μA, $V_{LCD}$ = 4.0V<br>Pins: COM1 - COM16 |
| Driver ON Resistance (SEG) | $R_{SEG}$ | - | - | 15K | KΩ | $I_O$ = ±50μA, $V_{LCD}$ = 4.0V<br>Pins: SEG1 - SEG80 |
| LCD Voltage | $V_{LCD}$ | 3.0 | - | 11 | V | VDD-V5, 1/4 bias or 1/5 bias |

**Note:** $F_{OSC}$ = 270KHz, VDD = 5.0V, pin E = "L", RS, R/W, DB0 - DB7 are open, all outputs are no loads.

### 7.5. AC Characteristics (VDD = 4.5V to 5.5V, $T_A$ = 25℃)

#### 7.5.1. Internal clock operation

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| OSC Frequency | $F_{OSC1}$ | 190 | 270 | 350 | KHz | VDD = 5.0V, Rf = 91KΩ±2% |

#### 7.5.2. External clock operation

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| External Frequency | $F_{OSC2}$ | 125 | 250 | 350 | KHz | |
| Duty Cycle | | 45 | 50 | 55 | % | |
| Rise/Fall Time | tr, tf | - | - | 0.2 | μs | |

### 7.5.3. Write mode (Writing Data from MPU to SPLC783A)

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| E Cycle Time | $t_C$ | 500 | - | - | ns | Pin E |
| E Pulse Width | $t_{PW}$ | 220 | - | - | ns | Pin E |
| E Rise/Fall Time | $t_R$, $t_F$ | - | - | 25 | ns | Pin E |
| Address Setup Time | $t_{SP1}$ | 40 | - | - | ns | Pins: RS, R/W, E |
| Address Hold Time | $t_{HD1}$ | 10 | - | - | ns | Pins: RS, R/W, E |
| Data Setup Time | $t_{SP2}$ | 60 | - | - | ns | Pins: DB0 - DB7 |
| Data Hold Time | $t_{HD2}$ | 10 | - | - | ns | Pins: DB0 - DB7 |

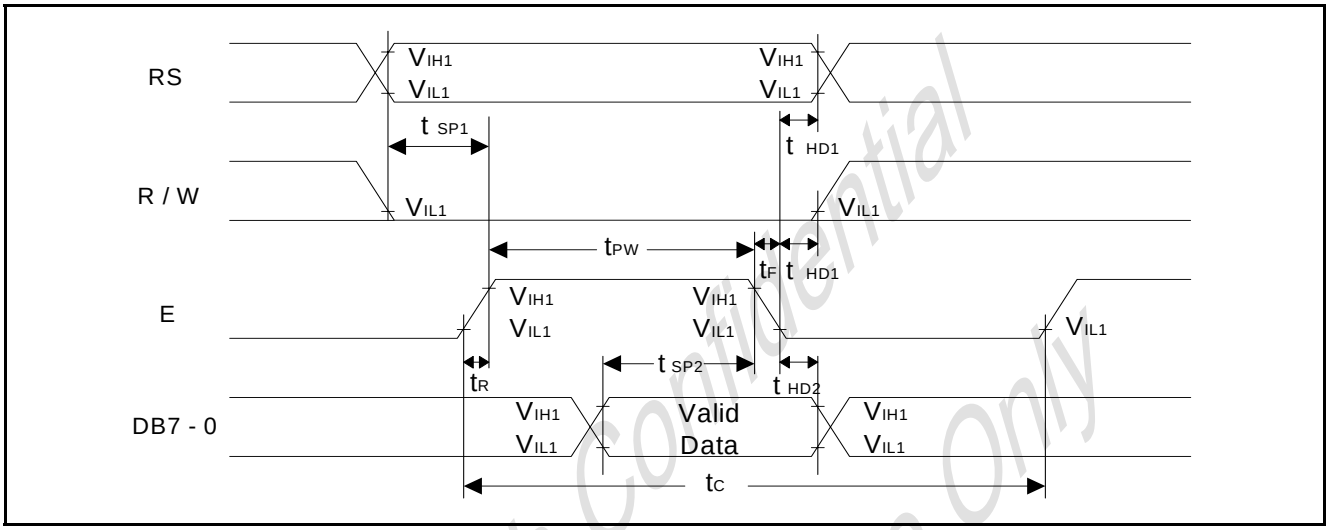
### 7.5.4. Read mode (Reading Data from SPLC783A to MPU)

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| E Cycle Time | $t_C$ | 500 | - | - | ns | Pin E |
| E Pulse Width | $t_W$ | 220 | - | - | ns | Pin E |
| E Rise/Fall Time | $t_R$, $t_F$ | - | - | 25 | ns | Pin E |
| Address Setup Time | $t_{SP1}$ | 40 | - | - | ns | Pins: RS, R/W, E |
| Address Hold Time | $t_{HD1}$ | 10 | - | - | ns | Pins: RS, R/W, E |
| Data Output Delay Time | $t_D$ | - | - | 120 | ns | Pins: DB0 - DB7 |
| Data hold time | $t_{HD2}$ | 20 | - | - | ns | Pin DB0 - DB7 |

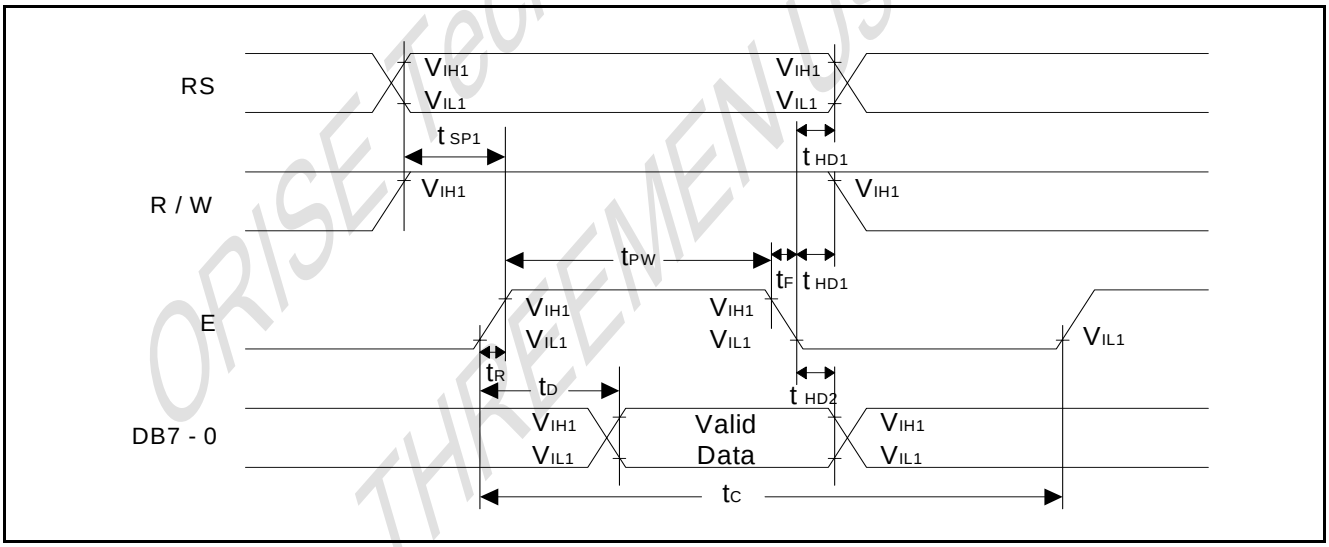
### 7.5.5. Interface mode with LCD Driver (SPLC100A1)

| Characteristics | Symbol | Limit | | | Unit | Test Condition |
|---|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | | |
| Clock pulse width high | $t_{PWH}$ | 800 | - | - | ns | Pins: CLK1, CLK2 |
| Clock pulse width low | $t_{PWL}$ | 800 | - | - | ns | Pins: CLK1, CLK2 |
| Clock setup time | $t_{CSP}$ | 500 | - | - | ns | Pins: CLK1, CLK2 |
| Data setup time | $t_{DSP}$ | 300 | - | - | ns | Pins: D |
| Data hold time | $t_{HD}$ | 300 | - | - | ns | Pins: D |
| M delay time | $t_D$ | -1000 | - | 1000 | ns | Pins: M |

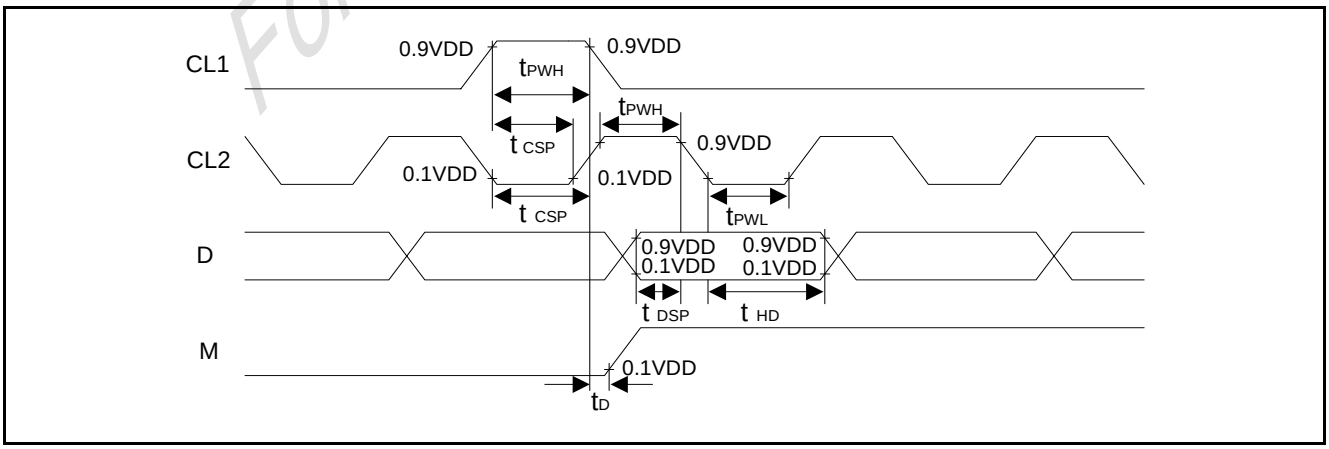
### 7.5.6. Write mode timing diagram (Writing Data from MPU to SPLC783A)




### 7.5.7. Read mode timing diagram (Reading Data from SPLC783A to MPU)



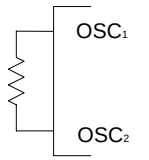

### 7.5.8. Interface mode with SPLC100A1 timing diagram



## 8. APPLICATION CIRCUITS

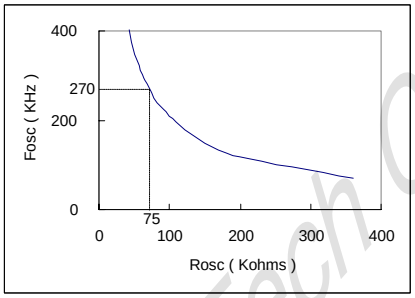
### 8.1. R-Oscillator

The oscillation resistor $R_f$ is used only for the internal oscillaotr operation mode.

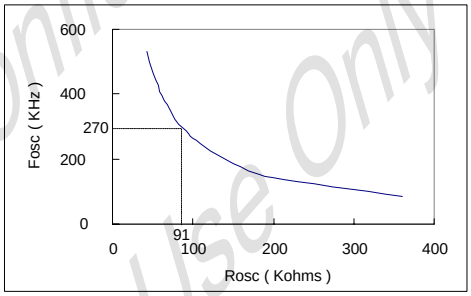



$R_f$ : 75KΩ ± 2% ( when VDD = 3.0V)
$R_f$ : 91KΩ ± 2% ( when VDD = 5.0V)

Since the oscillation frequency varies depending on the $OSC_1$ and $OSC_2$ pin capacitance, the wiring length to these pins should be minimized.



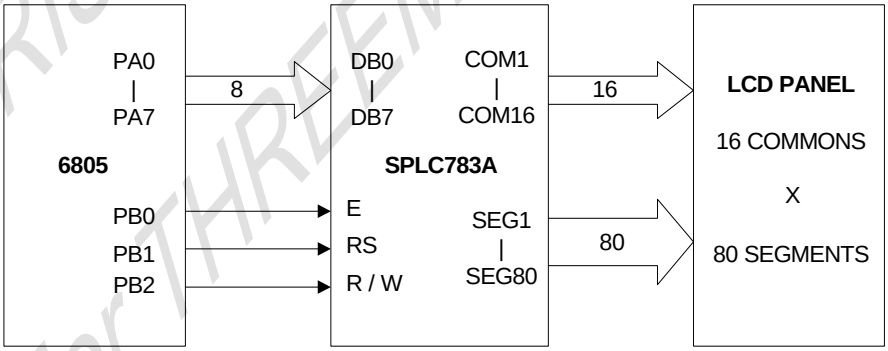

VDD = 3.0V



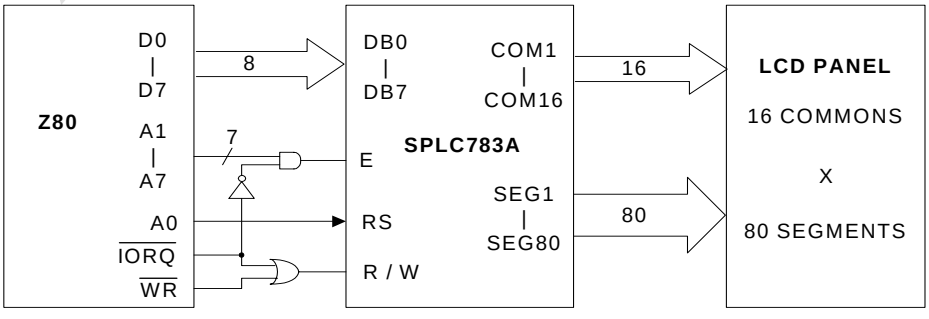

VDD = 5.0V

### 8.2. Interface to MPU

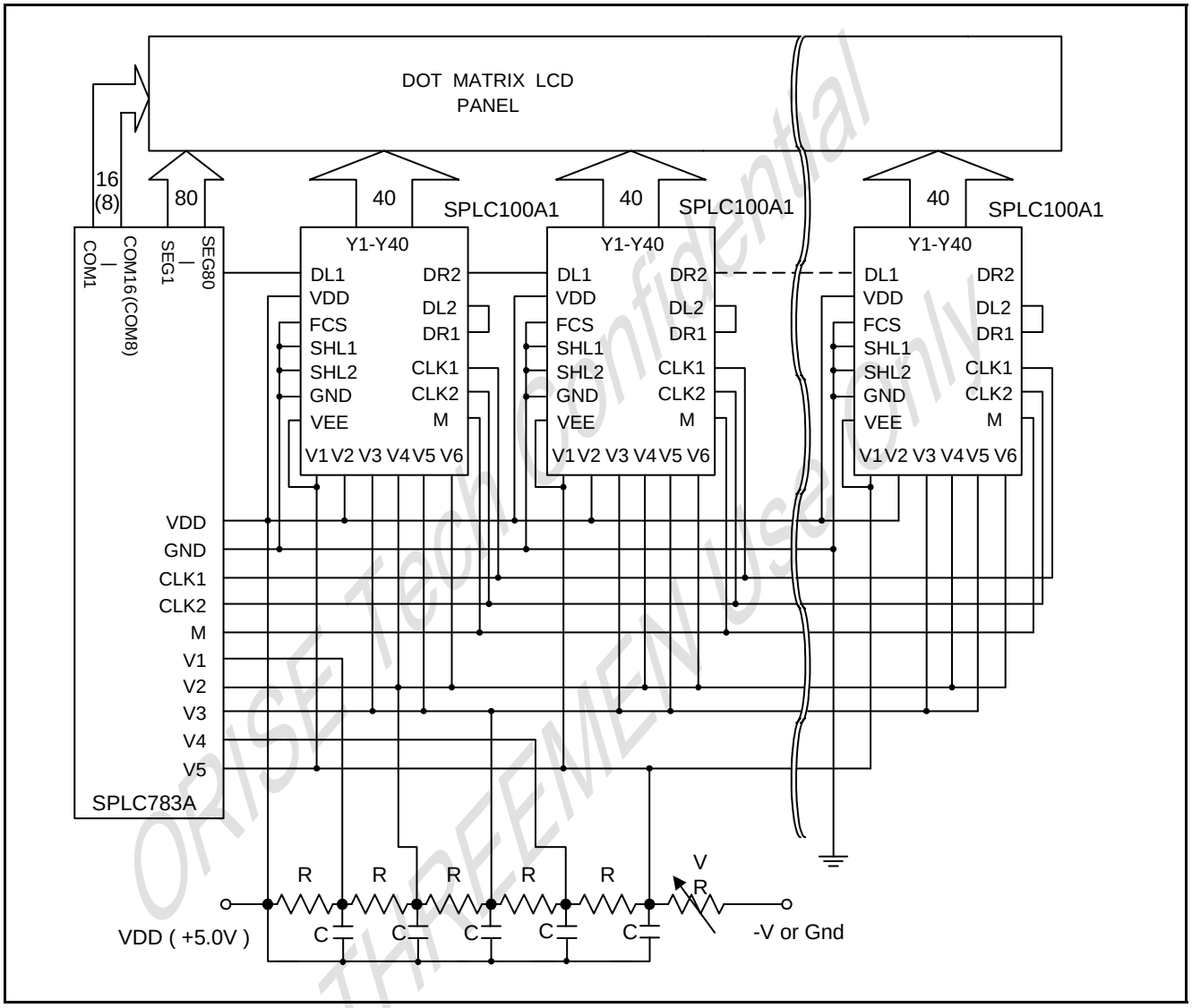
#### 8.2.1. Interface to 8-bit MPU (6805)



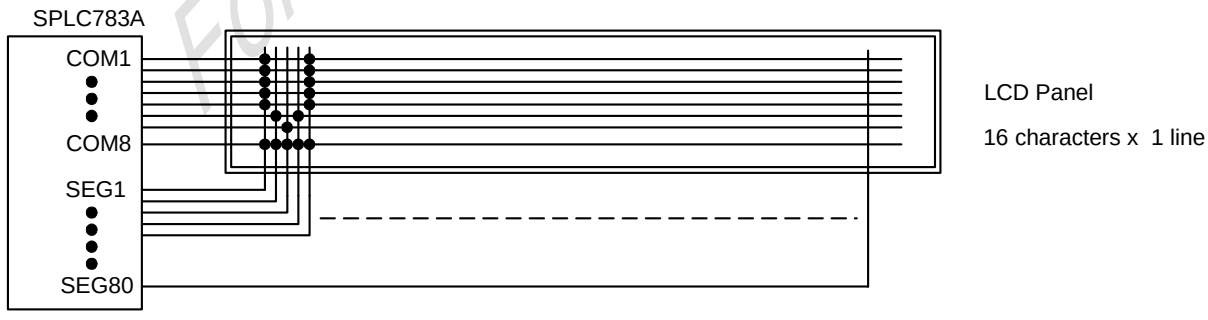

#### 8.2.2. Interface to 8-bit MPU (Z80)



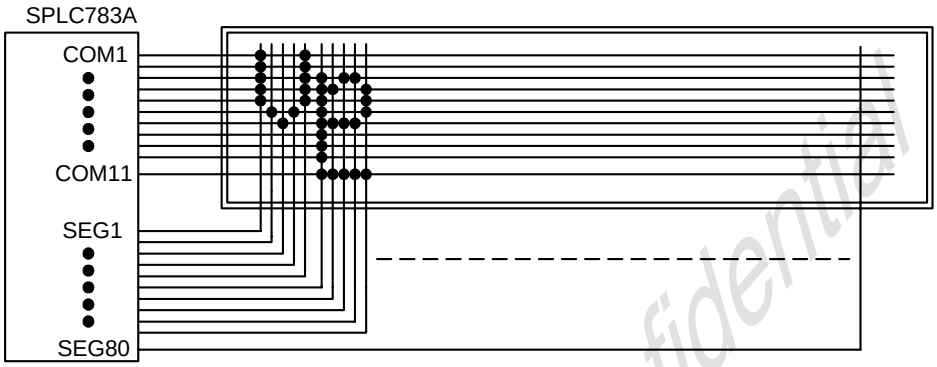
### 8.3. SPLC783A Application Circuit



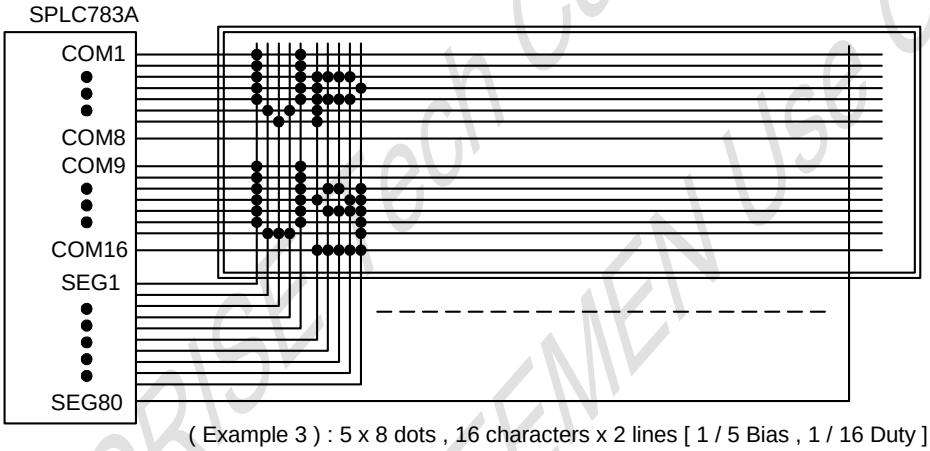

### 8.4. Applications for LCD



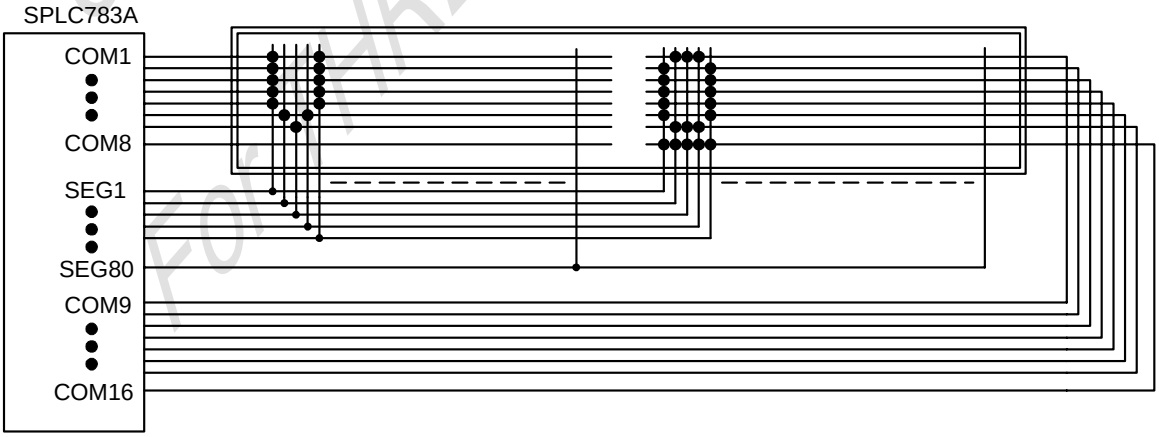

( Example 1 ) : 5 x 8 dots , 16 characters x 1 line [ 1 / 4 Bias , 1 / 8 Duty ]



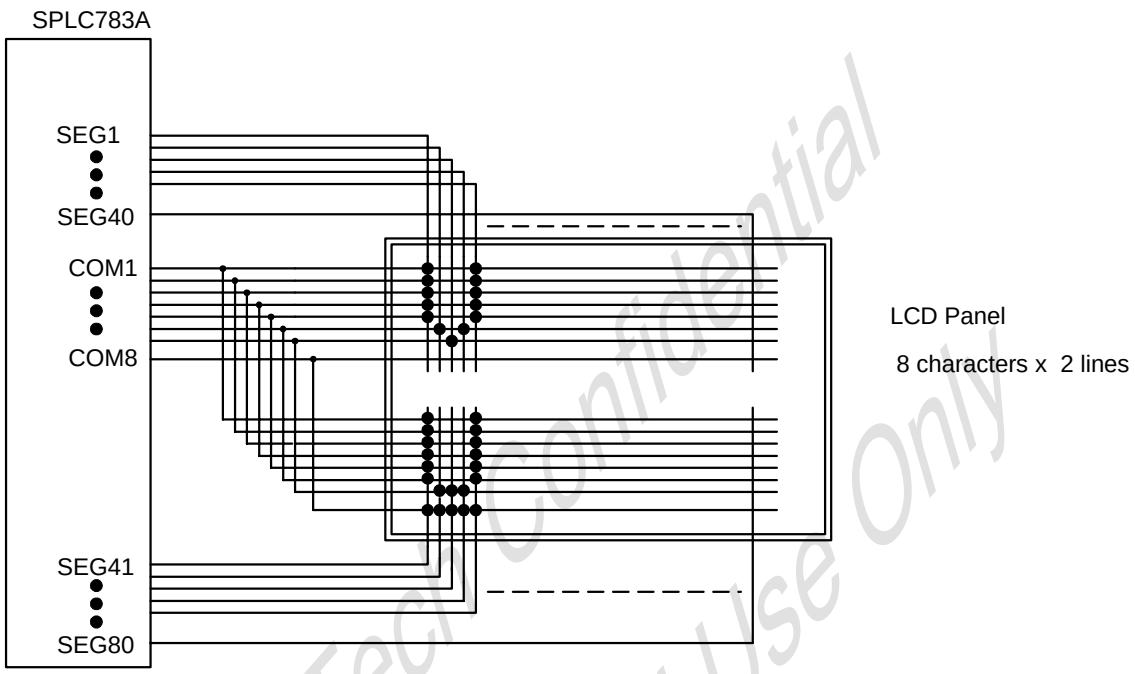

( Example 2 ) : 5 x 10 dots , 16 characters x 1 line [ 1 / 4 Bias , 1 / 11 Duty ]




( Example 3 ) : 5 x 8 dots , 16 characters x 2 lines [ 1 / 5 Bias , 1 / 16 Duty ]




( Example 4 ) : 5 x 8 dots , 32 characters x 1 line [ 1 / 5 Bias , 1 / 16 Duty ]

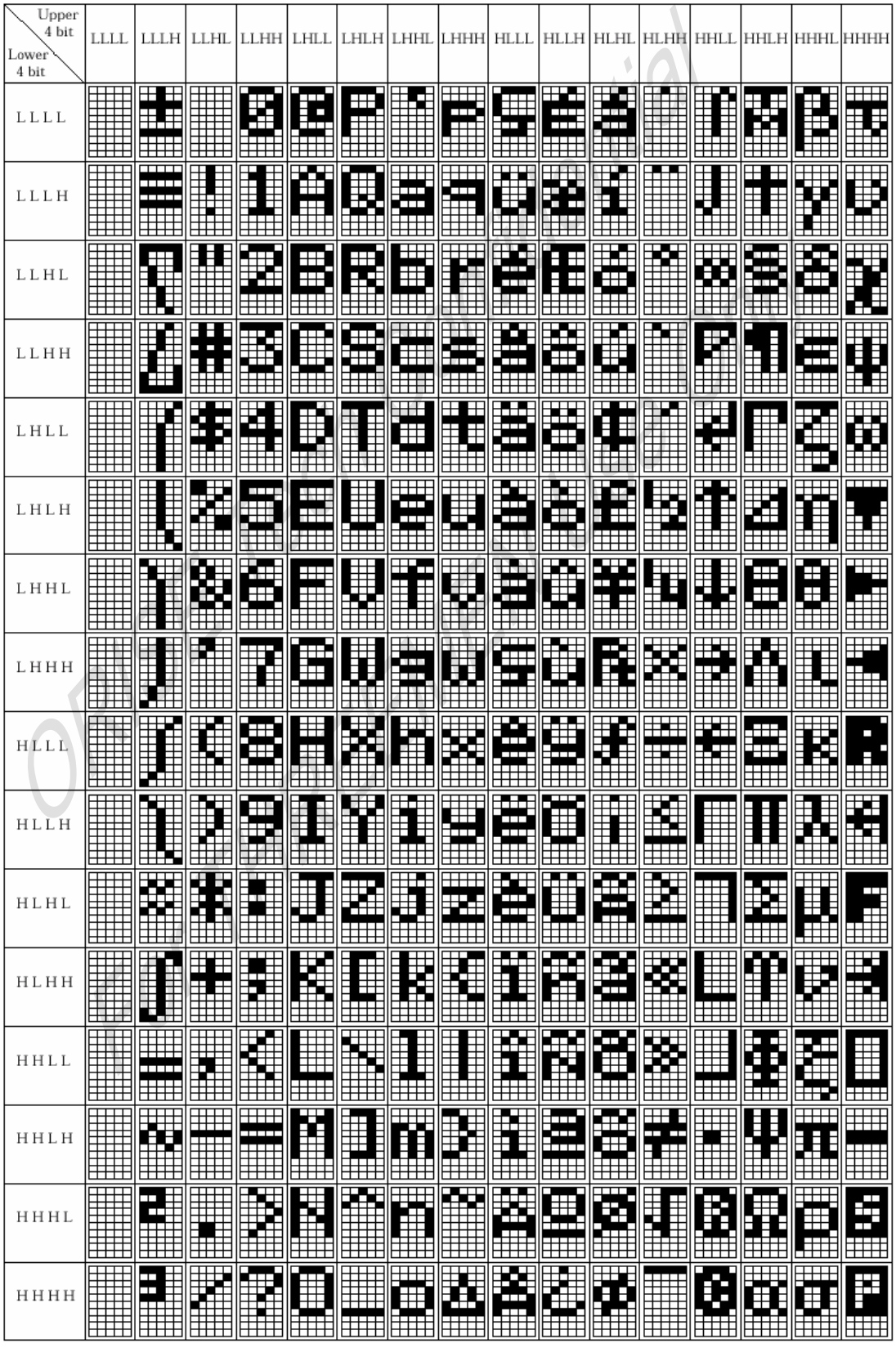



( Example 5 ) : 5 x 8 dots , 8 characters x 2 lines [ 1 / 4 Bias , 1 / 8 Duty ]

## 9. CHARACTER GENERATOR ROM

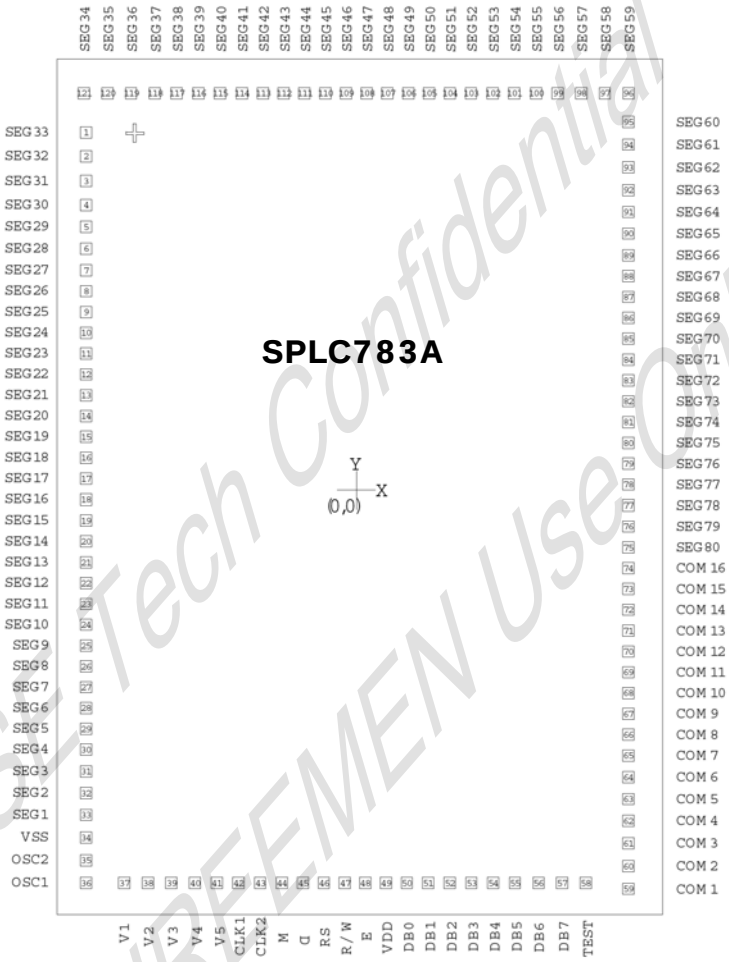
### 9.1. SPLC783A - 001

### 9.2. SPLC783A - 003



## 10. PACKAGE/PAD LOCATIONS

### 10.1. PAD Assignment




Chip Size: 3210μm x 4520μm

PAD Size: 90μm x 90μm

This IC substrate should be connected to VDD

**Note1:** Chip size included scribe line.

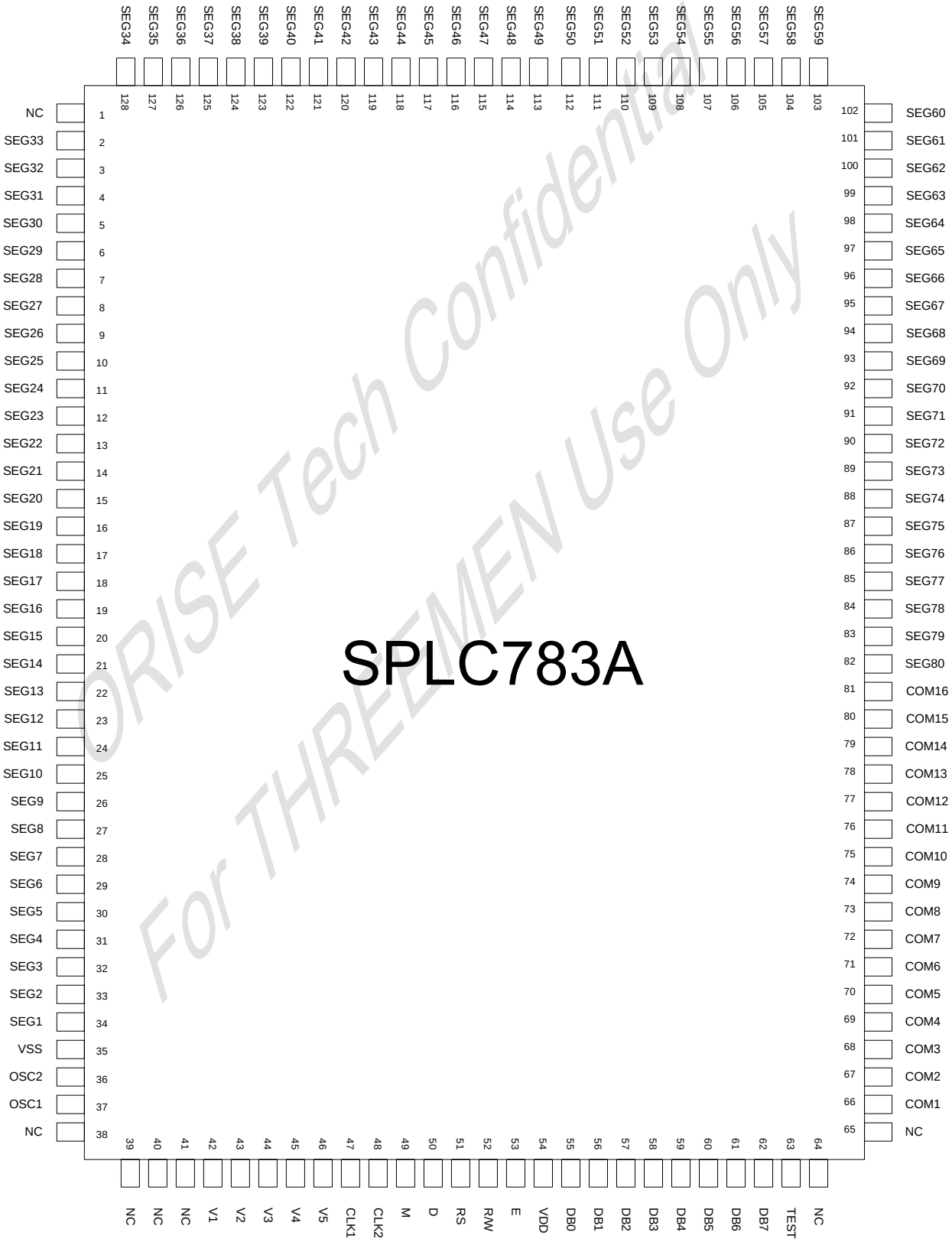
**Note2:** To ensure that the IC functions properly, please bond all of VDD and VSS pins.

**Note3:** The 0.1μF capacitor between VDD and VSS should be placed to IC as close as possible.

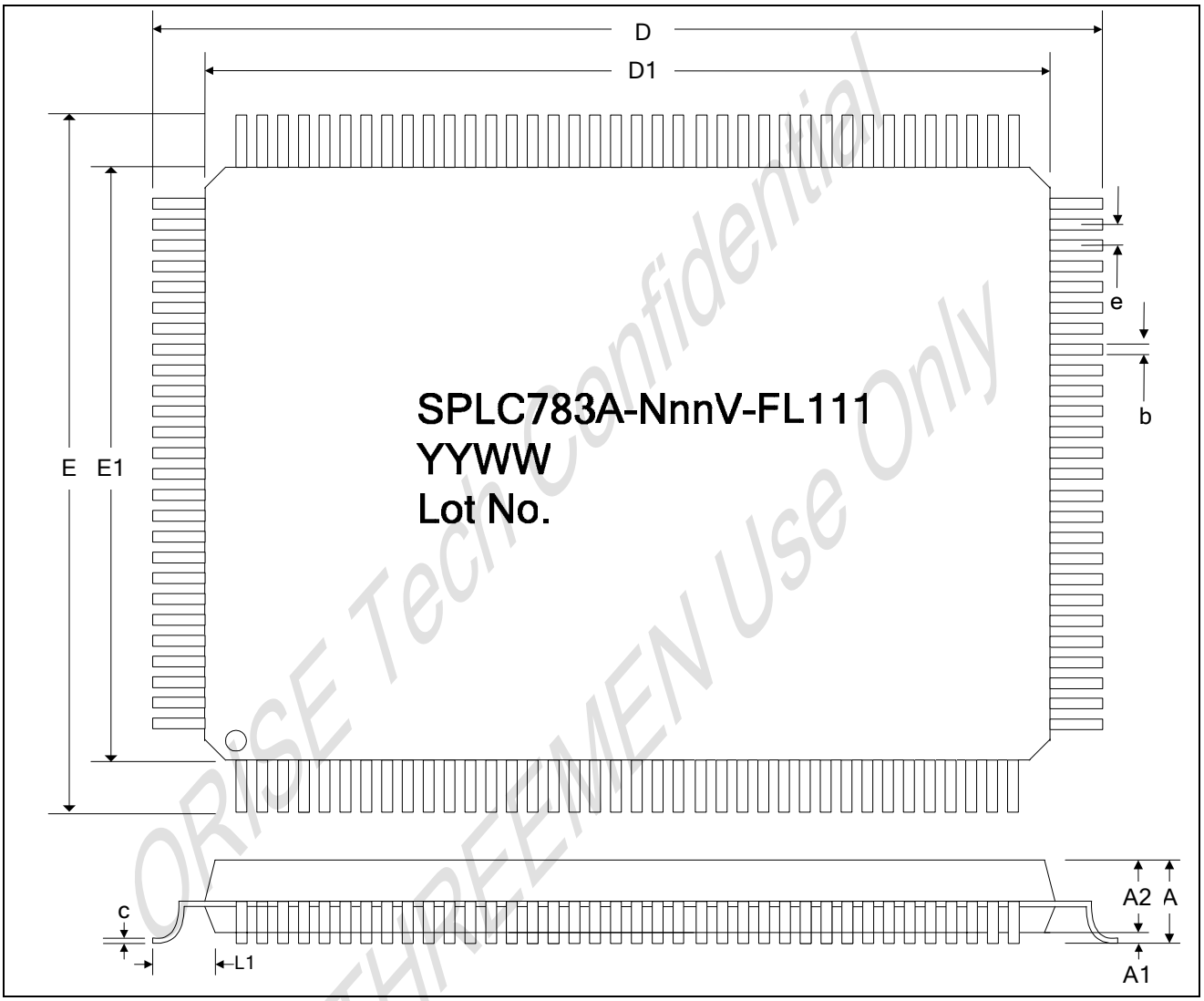
### 10.2. PAD Locations

| PAD No. | PAD Name | X | Y |
|---|---|---|---|
| 1 | SEG33 | -1433 | 1889 |
| 2 | SEG32 | -1433 | 1763 |
| 3 | SEG31 | -1433 | 1631 |
| 4 | SEG30 | -1433 | 1505 |
| 5 | SEG29 | -1433 | 1390 |
| 6 | SEG28 | -1433 | 1275 |
| 7 | SEG27 | -1433 | 1160 |
| 8 | SEG26 | -1433 | 1050 |
| 9 | SEG25 | -1433 | 940 |
| 10 | SEG24 | -1433 | 830 |
| 11 | SEG23 | -1433 | 720 |
| 12 | SEG22 | -1433 | 610 |
| 13 | SEG21 | -1433 | 500 |
| 14 | SEG20 | -1433 | 390 |
| 15 | SEG19 | -1433 | 280 |
| 16 | SEG18 | -1433 | 169 |
| 17 | SEG17 | -1433 | 59 |
| 18 | SEG16 | -1433 | -50 |
| 19 | SEG15 | -1433 | -160 |
| 20 | SEG14 | -1433 | -270 |
| 21 | SEG13 | -1433 | -380 |
| 22 | SEG12 | -1433 | -490 |
| 23 | SEG11 | -1433 | -600 |
| 24 | SEG10 | -1433 | -710 |
| 25 | SEG9 | -1433 | -820 |
| 26 | SEG8 | -1433 | -930 |
| 27 | SEG7 | -1433 | -1040 |
| 28 | SEG6 | -1433 | -1150 |
| 29 | SEG5 | -1433 | -1260 |
| 30 | SEG4 | -1433 | -1370 |
| 31 | SEG3 | -1433 | -1485 |
| 32 | SEG2 | -1433 | -1600 |
| 33 | SEG1 | -1433 | -1715 |
| 34 | VSS | -1433 | -1835 |
| 35 | OSC2 | -1433 | -1955 |
| 36 | OSC1 | -1433 | -2076 |
| 37 | V1 | -1230 | -2076 |
| 38 | V2 | -1105 | -2076 |
| 39 | V3 | -980 | -2076 |
| 40 | V4 | -855 | -2076 |
| 41 | V5 | -740 | -2076 |
| 42 | CLK1 | -625 | -2076 |
| 43 | CLK2 | -510 | -2076 |
| 44 | M | -395 | -2076 |
| 45 | D | -282 | -2076 |
| 46 | RS | -172 | -2076 |
| 47 | R/W | -62 | -2076 |
| 48 | E | 47 | -2076 |
| 49 | VDD | 157 | -2076 |
| 50 | DB0 | 267 | -2076 |
| 51 | DB1 | 379 | -2076 |
| 52 | DB2 | 494 | -2076 |
| 53 | DB3 | 609 | -2076 |
| 54 | DB4 | 724 | -2076 |
| 55 | DB5 | 840 | -2076 |
| 56 | DB6 | 965 | -2076 |
| 57 | DB7 | 1090 | -2076 |
| 58 | TEST | 1215 | -2076 |
| 59 | COM1 | 1440 | -2106 |
| 60 | COM2 | 1440 | -1986 |
| 61 | COM3 | 1440 | -1866 |
| 62 | COM4 | 1440 | -1746 |
| 63 | COM5 | 1440 | -1631 |
| 64 | COM6 | 1440 | -1516 |
| 65 | COM7 | 1440 | -1401 |
| 66 | COM8 | 1440 | -1291 |
| 67 | COM9 | 1440 | -1181 |
| 68 | COM10 | 1440 | -1071 |
| 69 | COM11 | 1440 | -961 |
| 70 | COM12 | 1440 | -851 |
| 71 | COM13 | 1440 | -741 |
| 72 | COM14 | 1440 | -631 |
| 73 | COM15 | 1440 | -521 |
| 74 | COM16 | 1440 | -411 |
| 75 | SEG80 | 1440 | -301 |
| 76 | SEG79 | 1440 | -191 |
| 77 | SEG78 | 1440 | -81 |
| 78 | SEG77 | 1440 | 28 |
| 79 | SEG76 | 1440 | 138 |
| 80 | SEG75 | 1440 | 248 |
| 81 | SEG74 | 1440 | 358 |
| 82 | SEG73 | 1440 | 468 |
| 83 | SEG72 | 1440 | 578 |
| 84 | SEG71 | 1440 | 688 |
| 85 | SEG70 | 1440 | 799 |
| 86 | SEG69 | 1440 | 909 |
| 87 | SEG68 | 1440 | 1019 |
| 88 | SEG67 | 1440 | 1129 |
| 89 | SEG66 | 1440 | 1239 |
| 90 | SEG65 | 1440 | 1354 |
| 91 | SEG64 | 1440 | 1469 |
| 92 | SEG63 | 1440 | 1584 |
| 93 | SEG62 | 1440 | 1704 |
| 94 | SEG61 | 1440 | 1824 |
| 95 | SEG60 | 1440 | 1944 |
| 96 | SEG59 | 1442 | 2096 |
| 97 | SEG58 | 1317 | 2096 |
| 98 | SEG57 | 1192 | 2096 |
| 99 | SEG56 | 1067 | 2096 |
| 100 | SEG55 | 952 | 2096 |
| 101 | SEG54 | 837 | 2096 |
| 102 | SEG53 | 722 | 2096 |
| 103 | SEG52 | 607 | 2096 |
| 104 | SEG51 | 495 | 2096 |
| 105 | SEG50 | 385 | 2096 |
| 106 | SEG49 | 275 | 2096 |
| 107 | SEG48 | 165 | 2096 |
| 108 | SEG47 | 55 | 2096 |
| 109 | SEG46 | -55 | 2096 |
| 110 | SEG45 | -165 | 2096 |
| 111 | SEG44 | -275 | 2096 |
| 112 | SEG43 | -385 | 2096 |
| 113 | SEG42 | -495 | 2096 |
| 114 | SEG41 | -607 | 2096 |
| 115 | SEG40 | -722 | 2096 |
| 116 | SEG39 | -837 | 2096 |
| 117 | SEG38 | -952 | 2096 |
| 118 | SEG37 | -1069 | 2096 |
| 119 | SEG36 | -1194 | 2096 |
| 120 | SEG35 | -1319 | 2096 |
| 121 | SEG34 | -1444 | 2096 |

### 10.3. PIN Assignment



### 10.4. Package Information (Lead Free Package)

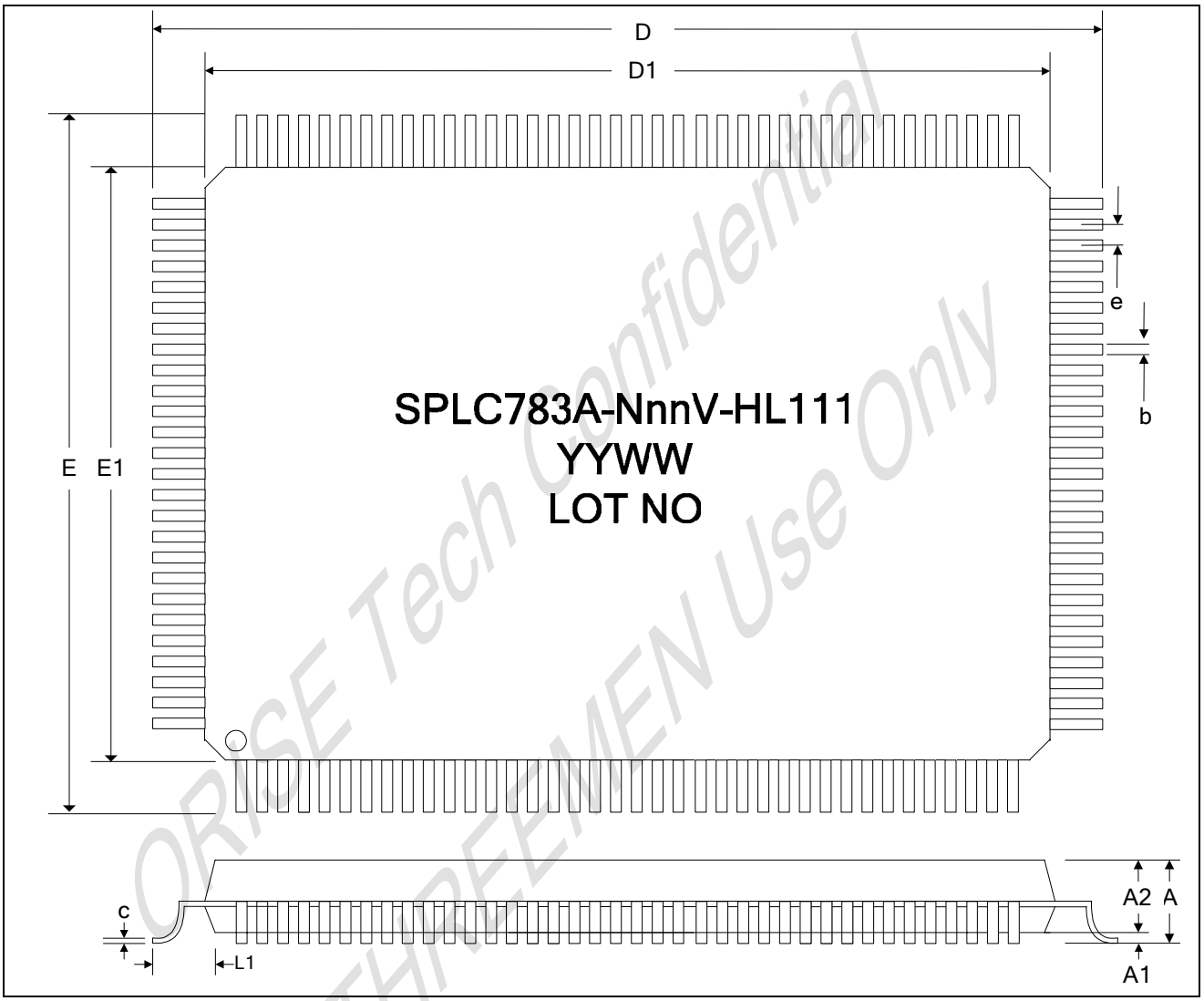





| Symbol | Min. | Nom. | Max. |
|---|---|---|---|
| A | - | - | 1.60 |
| A1 | 0.05 | - | 0.15 |
| A2 | 1.35 | 1.40 | 1.45 |
| D | 21.90 | 22.00 | 22.10 |
| D1 | 19.90 | 20.00 | 20.10 |
| E | 15.90 | 16.00 | 16.10 |
| E1 | 13.90 | 14.00 | 14.10 |
| e | 0.50 BSC. | | |
| b | 0.17 | 0.22 | 0.27 |
| c | 0.09 | - | 0.20 |
| L1 | 1.00 REF | | |

Unit: Millimeter

### 10.5. Package Information (Green Package)

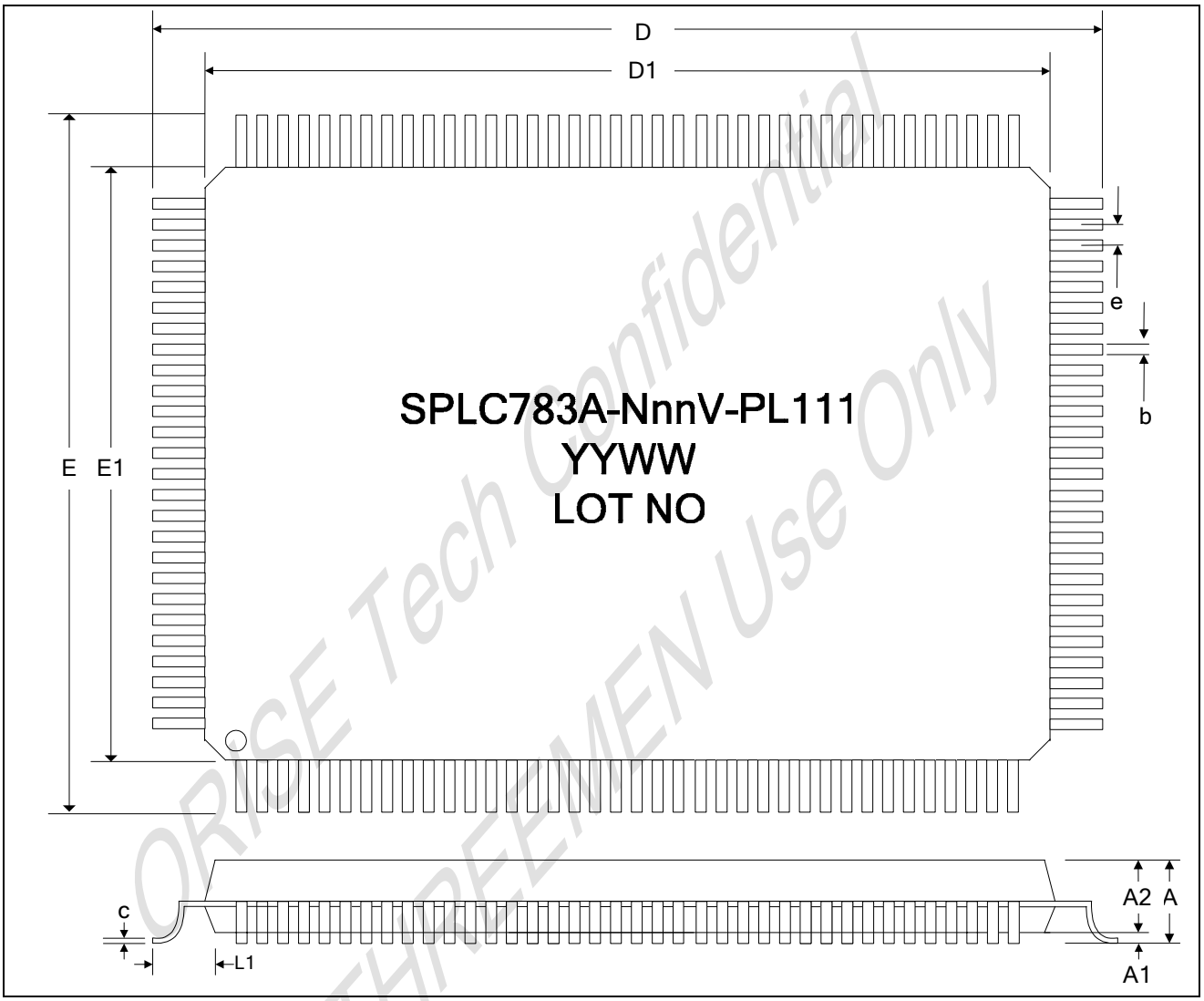





| Symbol | Min. | Nom. | Max. |
|---|---|---|---|
| A | - | - | 1.60 |
| A1 | 0.05 | - | 0.15 |
| A2 | 1.35 | 1.40 | 1.45 |
| D | 21.90 | 22.00 | 22.10 |
| D1 | 19.90 | 20.00 | 20.10 |
| E | 15.90 | 16.00 | 16.10 |
| E1 | 13.90 | 14.00 | 14.10 |
| e | 0.50 BSC. | | |
| b | 0.17 | 0.22 | 0.27 |
| c | 0.09 | - | 0.20 |
| L1 | 1.00 REF | | |

Unit: Millimeter

### 10.6. Package Information (General Package)






| Symbol | Min. | Nom. | Max. |
|---|---|---|---|
| A | - | - | 1.60 |
| A1 | 0.05 | - | 0.15 |
| A2 | 1.35 | 1.40 | 1.45 |
| D | 21.90 | 22.00 | 22.10 |
| D1 | 19.90 | 20.00 | 20.10 |
| E | 15.90 | 16.00 | 16.10 |
| E1 | 13.90 | 14.00 | 14.10 |
| e | 0.50 BSC. | | |
| b | 0.17 | 0.22 | 0.27 |
| c | 0.09 | - | 0.20 |
| L1 | 1.00 REF | | |

Unit: Millimeter

## 11. LEAD FRAME PACKAGE PCB DESIGN AND MANUFACTURING GUIDELINES

### 11.1. Purpose

The purpose of this specification is to identify plastic surface mount devices (SMDs) those are sensitive to moisture-induced stress, so that they can be properly design PCB and assembly packaged, stored and handled to avoid subsequent mechanical damage during the assembly solder reflow attachment and /or repair operation.

### 11.2. Scope

#### 11.2.1. PCB layout guideline

#### 11.2.2. PCB process

#### 11.2.3. Storage Condition and Period for Package

#### 11.2.4. Recommended SMT Temperature Profile

### 11.3. Noun definition

#### 11.3.1. NSMD: Non Solder Mask Defined

#### 11.3.2. SMD: Solder Mask Defined

#### 11.3.3. CSP: Chip scale Package

#### 11.3.4. PCB :Printed Circuit Board

### 11.4. Responsibility unity:

ORISE Quality Assurance unity

### 11.5. Contents

#### 11.5.1. Applicable documents

IPC-SM-782: Surface Mount Design & Land Pattern Standard

IPC-7351Generic Requirements for Surface Mount Design and Land Pattern Standard.

IPC-7525: Stencil Design Guidelines

J-STD-020: IPC/JEDEC Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Device

IPC JEDEC: J-STD-033A Standard for Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices

IPC-HDBK-001: Handbook & Guide to the Requirements of Soldered Electronic Assemblies with Amendment 1

IPC -6016: Qualification & Performance Specification for High Density Interconnect (HDI) Layers or Boards

IPC-STD-003: Solderability Tests for Printed Boards

JESD22-B111: Board Level Drop Test of Components for Handheld Electronic Products

JESD22-B110: Subassembly Mechanical Shock

IPC-A-610: Acceptability of Electronic Assemblies

#### 11.5.2. PCB layout guideline

PCB designer comply with IPC-SM-782 and IPC-7095 requirements is recommended

#### 11.5.3. PCB process

11.5.3.1. Board material

The Glass transition temperature (Tg) of Board material greater than 170 degree C is recommended for Pb-free and Green package.

11.5.3.2. Surface Finishes

In order to achieve high assembly yields, use of a surface finish that is planar

And has good solderability performance is important. Below methods are all known to provide an acceptable land pad surface.

*OSP (Organic Solderability Preservative)

*Nihau (Electroplated nickel /gold)

*Immersion Ag

*Immersion Sn

11.5.3.3. Solder Paste: No clean flux is recommended.

11.5.3.4. Stencil Design Guidelines: Refer to IPC-7525 Stencil Design Guidelines process

11.5.3.5. Reflow Oven: Forced convection reflow with nitrogen is recommended for Pb-free and Green package..

11.5.3.6. Reflow profile: Using more than 8 zone oven is recommended for Pb-free and Green package.

11.5.3.7. To use IPC-A-610 is recommended for soldered electrical and electronic assemblies.

**11.5.4. Storage condition and period for package**

Orise technology evaluates all plastic surface mount devices (SMDs) to ICP/JEDEC J-STD-020A, moisture/reflow sensitivity classification for non-hermetic solid state surface mount devices, or refers to IPC JEDEC J-STD-033A Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices

11.5.4.1. The primary facts for the package storage include oxidation, static, and therefore, the following rules are recommended to be applied for the storage.

11.5.4.2. The storage temperature should be 25℃ ± 5℃, and the humidity should be in the range of 50% ± 10% R.H. after opening the dry pack.

After the dry bag is opened, devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing.

11.5.4.3. Must be:

a. Mounted within 168 hours(Level 3) and 72 hours(Level 4) at factory conditions of ≦ 30℃/ 60% R.H. or

b. Stored at ≦ 20% R.H.

11.5.4.4. Devices require baking, before mounting, if:

a. Humidity Indicator Card shown warning message when read at 25℃±5℃, or

b. 11.5.4.3 is not met.

11.5.4.5. If baking is required. Devices may be baking for:

a. 192 hour at 40℃+5℃/-0℃ and <5% R.H. for low temperature device containers, or

b. 24 hours at 125±5℃ for high temperature device containers

11.5.4.6. The storage condition should be consistent with the operation condition to prevent dewing phenomena.

11.5.4.7. The storage location should be kept away from water and smoke; an isolated area with positive pressure control is preferred.

11.5.4.8. For a long-term storage, it is recommended to keep in a container with Nitrogen in it.

11.5.4.9. Avoid heavy objects stacked on the pack.

11.5.4.10. Avoid the static damage; use an anti-static bag for the package.

**11.5.5. The classification of moisture sensitivity for Orise's product packages are shown in the following**

(1) For General Packages

| Package | Moisture sensitivity level | Max. Reflow temperature | Floor life storage condition | Dry pack |
|---|---|---|---|---|
| LQFP | LEVEL 3 | 220 +5/-0℃ | 168Hrs @ ≦ 30℃/ 60% R.H. | Yes |

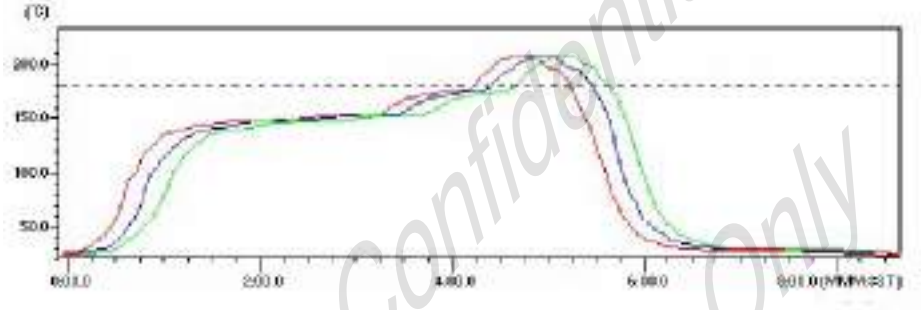
(2) For Lead Free / Green Packages

| Package | Moisture sensitivity level | Max. Reflow temperature | Floor life storage condition | Dry pack |
|---|---|---|---|---|
| LQFP | LEVEL 3 | 255 +5/-0℃ | 168Hrs @ ≦ 30℃/ 60% R.H. | Yes |

### 11.5.6. Recommended SMT Temperature Profile

This “Recommended” temperature profile is a rough guideline for SMT process reference. Most of ORISE leadframe base product choice Matte Tin and Sn/Bi for plating recipe. For PPF (Pre-Plated Frame) product with 63/37 solder paste, we recommend 240℃~245℃ for peak temperature.

**Recommended Reflow Profile for 63/37 Solder Paste or Cu lead frame**

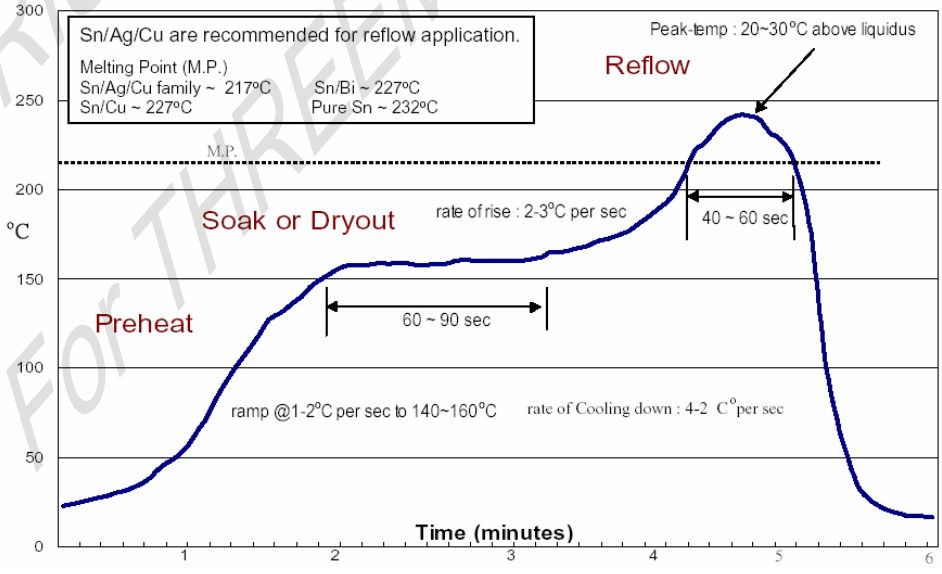


*This profile is designed for use with Sn63 or Sn62 and can serve as a general guideline in establishing a reflow profile.*

**Reflow Profile:**

- Heating-up @1~3°C per sec to 140°C
- Preheat @ 140-150°C for 120 ~ 160 sec
- Ramp @ 2~3 °C per sec to peak temperature (220 ~ 225 °C). Temperature over 183°C for 45~ 75 sec
- Cooling down to room temperature @4~2°C per sec to avoid undesired intermatalic compound layer

**Recommended Reflow Profile for Lead-free Solder Paste or PPF lead frame**



### 11.6. References

IPC:

http://www.ipc.org

*NEMI (National Electronics Manufacturing Initiative)

http://www.nemi.org

*HDPUG (High Density Package Users Group)

http://www.hdpug.org

*JEDEC (Joint Electronic Device Engineering Council)

http://www.jedec.org

*JEITA (Japan Electronic Industry Association)

http://www.jeita.org

## 12. DISCLAIMER

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## 13. REVISION HISTORY

| Date | Revision # | Description | Page |
|---|---|---|---|
| APR. 12, 2007 | 1.7 | 1. Update “3. ORDERING INFORMATION” | 4 |
| | | 2. Add “10.4. Package Information (Lead Free Package)” | 38 |
| | | 3. Modify “10.5. Package Information (Green Package)” | 39 |
| | | 4. Add “10.6. Package Information (General Package)” | 40 |
| NOV. 22, 2006 | 1.6 | 1. Modify Ordering information | 4 |
| | | 2. Modify 10.3 Package Information | 39 |
| | | 3. Remove 10.4 Storage Condition and Period for Package | |
| | | 4. Remove 10.5 Recommended SMT Temperature Profile | |
| | | 5. Move 5.1 PIN Map to 10.3 PIN Assignment | 38 |
| | | 6. Add LEAD FRAME PACKAGE PCB DESIGN AND MANUFACTURING GUIDELINES | 40-43 |
| AUG. 31, 2006 | 1.5 | Add PAD Assignment / PAD Locations | 35 - 37 |
| MAR. 10, 2005 | 1.4 | 1. Modify 8.1 and 8.2 code numbers from 2 digits to 3 digits | 33, 34 |
| | | 2. Add Green Package Product Number | 35 |
| | | 3. Add sections 9.4 and 9.5 | 36 |
| | | 4. Correct pin name: from RW to R/W | 5, 9 |
| | | | 19, 20 |
| APR. 01, 2004 | 1.3 | 1. Add min. and max. value in Instruction Table | 9 |
| | | 2. Add 8-bit/4-bit data transfer timing sequence example | 19 - 20 |
| NOV. 25, 2003 | 1.2 | 1. Add package information: LQFP 128 pin | 5, 6, 34 |
| | | 2. Remove “*9. PACKAGE/PAD LOCATIONS*” | |
| SEP. 27, 2002 | 1.1 | Correct “*9. PACKAGE/PAD LOCATIONS*” | 31 - 33 |
| OCT. 02, 2001 | 1.0 | Original | |